

# The CMS phase-2 High Granularity CALorimeter

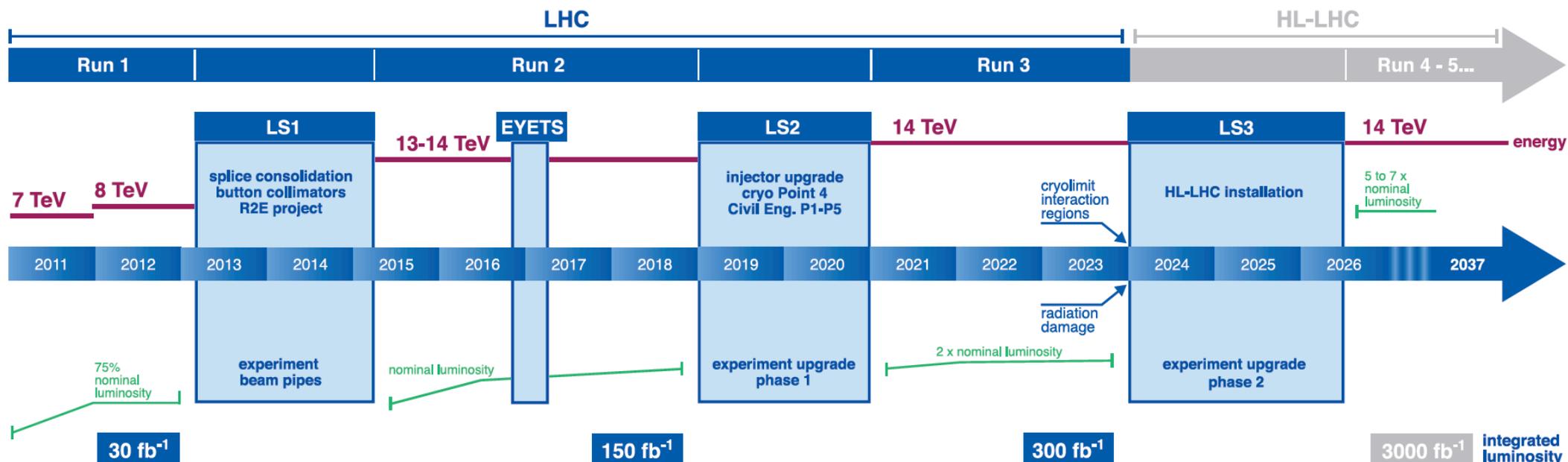


**Stathes Paganis, NTU, on behalf of the CMS collaboration**  
**ALCW, Fukuoka, 日本, May 2018**

# Outline

- Phase 2 requirements and the case for HGICAL
- Brief description of the detector design
  - Geometry, Sensors, Modules, Electronics.
- Reconstruction and Performance
- This presentation is based on the detailed review:  
[Dave Barney, CERN EP Seminar, 20 April 2018.](#)

# High Luminosity LHC



## HL-LHC:

levelled  $\mathcal{L} = 5 \times 10^{34} \text{cm}^{-2}\text{s}^{-1}$  and pileup 140, with potential for 50% higher  $\mathcal{L}$  & pileup

Physics reach will include SM & Higgs, with searches for BSM including reactions initiated by Vector Boson Fusion (VBF) and including **highly-boosted objects**

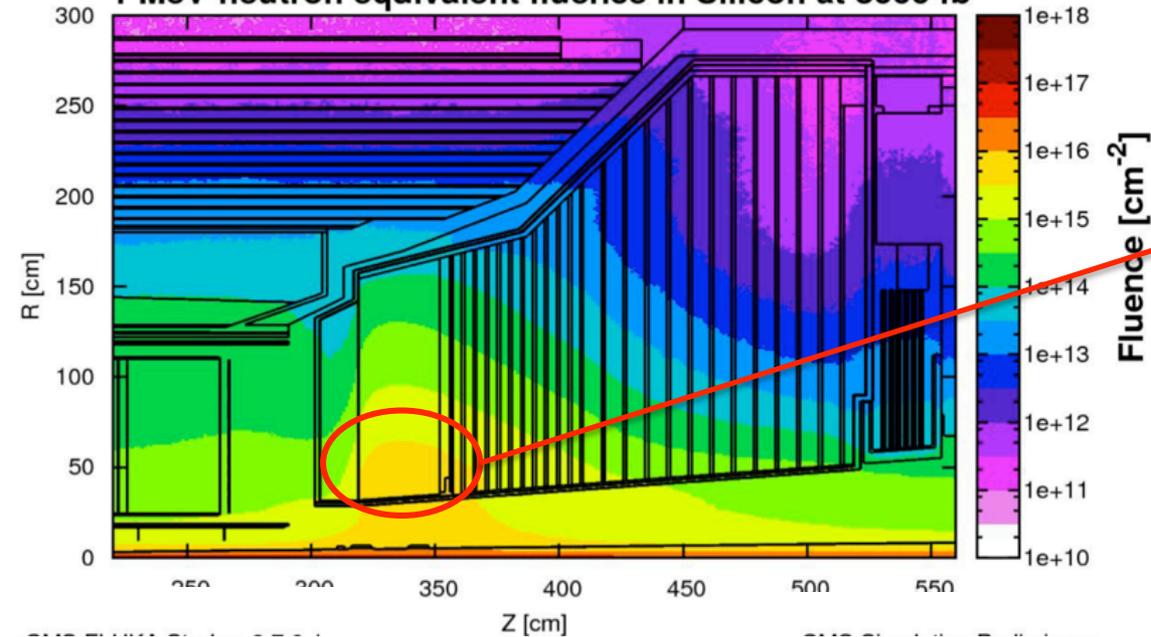
→ Narrow ( $\tau$ ) jets or merged (hadronic decays of W, Z) jets

→ Ideally want to trigger on these narrow VBF & merged jets

# Existing CMS endcap calorimeters cannot cope with the expected radiation or pileup @ HL-LHC

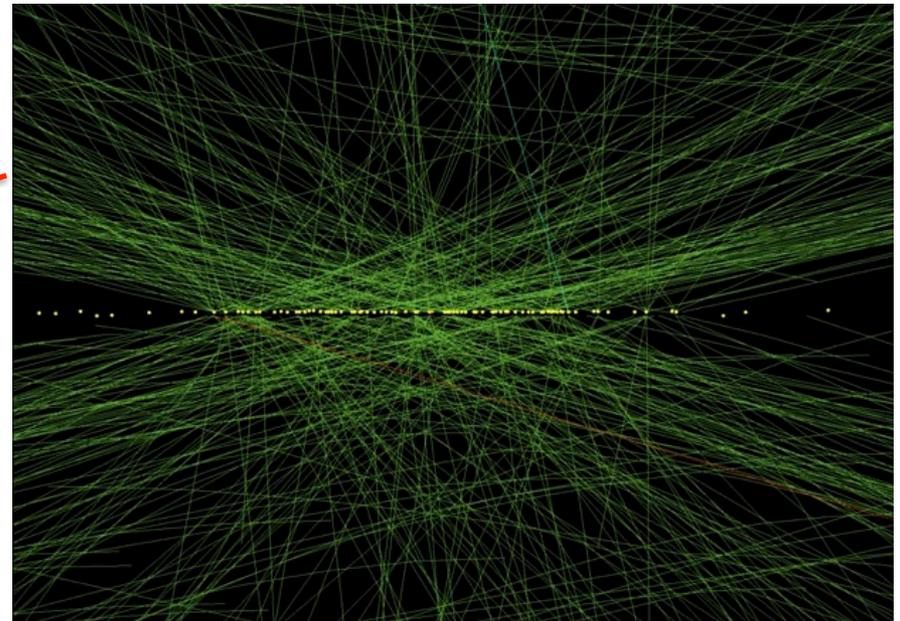
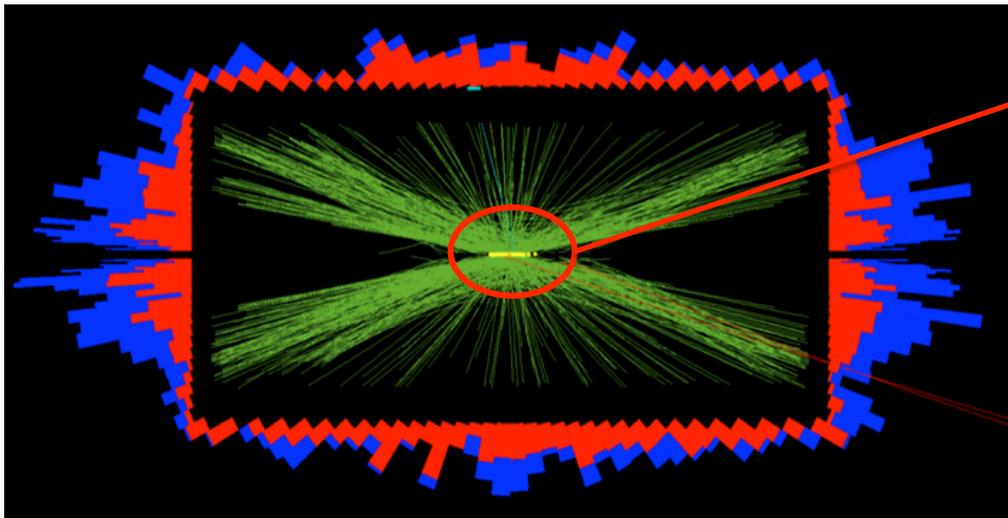
CMS p-p collisions at 7 TeV per beam

1 MeV-neutron equivalent fluence in Silicon at 3000 fb<sup>-1</sup>

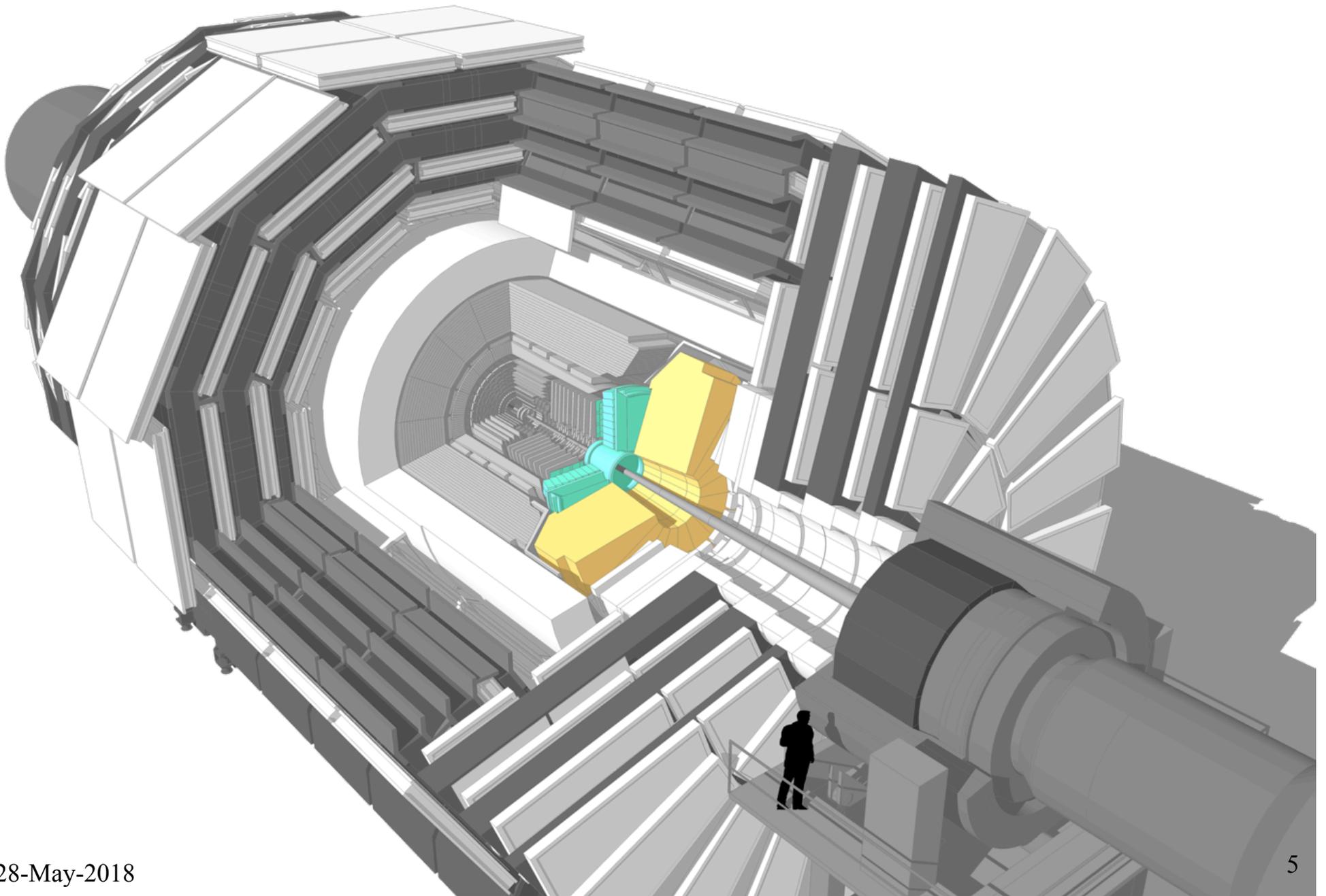


**CMS @ HL-LHC:**

$\sim 1 \times 10^{16}$  1 MeV  $n_{\text{eq}}$  cm<sup>-2</sup> @ 3ab<sup>-1</sup>  
and up to **2 MGy** absorbed dose  
in endcap calorimeters



# CMS will replace its endcap calos for HL-LHC: the **H**igh **G**ranularity **CAL**orimeter



# Need for good Jet Energy Resolution

Multi-jet final states (outgoing quarks, gluons)

Missing energy relies upon accurate jet energy measurements

Need to separate heavy bosons (W, Z, H) in hadronic decays

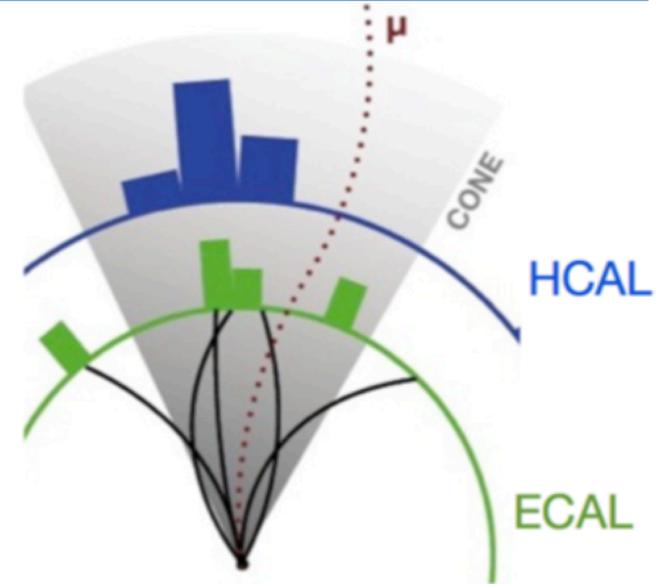
## “Typical” jet:

~62% charged particles (mainly hadrons)

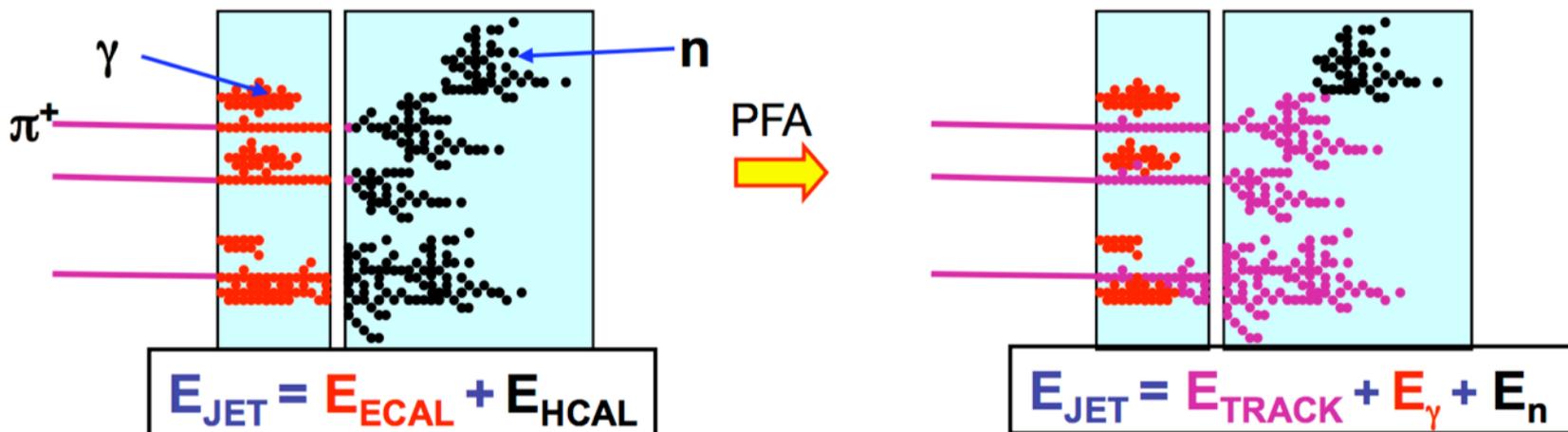
~27% photons

~10% neutral hadrons

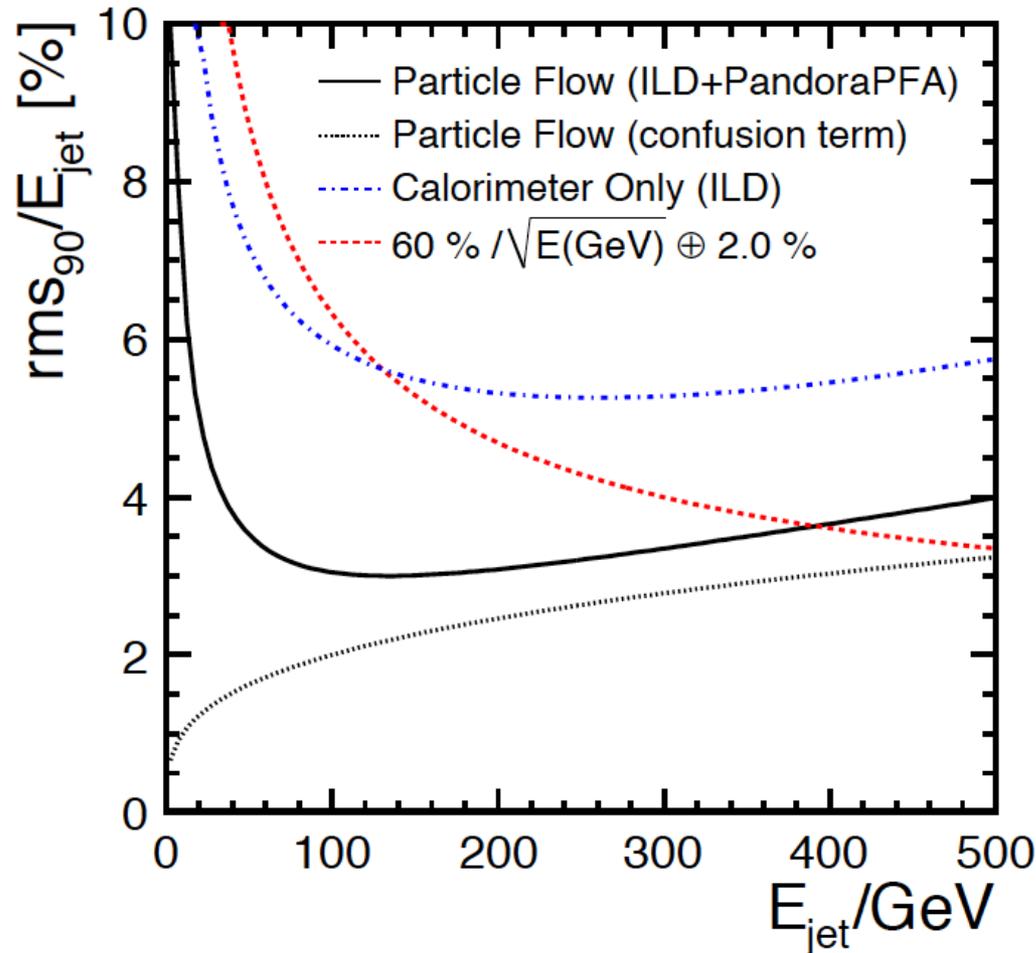
~1% neutrinos



Particle Flow: use all available information for jet reconstruction



# Particle Flow and HAD resolution



(from Katja Kruger's talk from BTTB5)

- PFA improves resolution.
- At high energies the correct track-cluster association becomes significant: **need for high granularity**
- At low energies dominated by calorimetric resolution: **need for good energy resolution**

# Requirements → Choice

- Low cost/area active materials.
- Rad tolerant on-detector electronics
- High bandwidth data transmission, powerful FPGAs for off-detector electronics
- High transverse and longitudinal readout granularity for good PID, two-shower separation (EM and hadronic), good Energy resolution.
- Radiation hard active materials.

Inspired by the work of CALICE (many people from CALICE work in HGCAL)

## **A silicon-sensor-based sampling calorimeter**

(absorber materials – W, Pb, Cu, Stainless Steel)

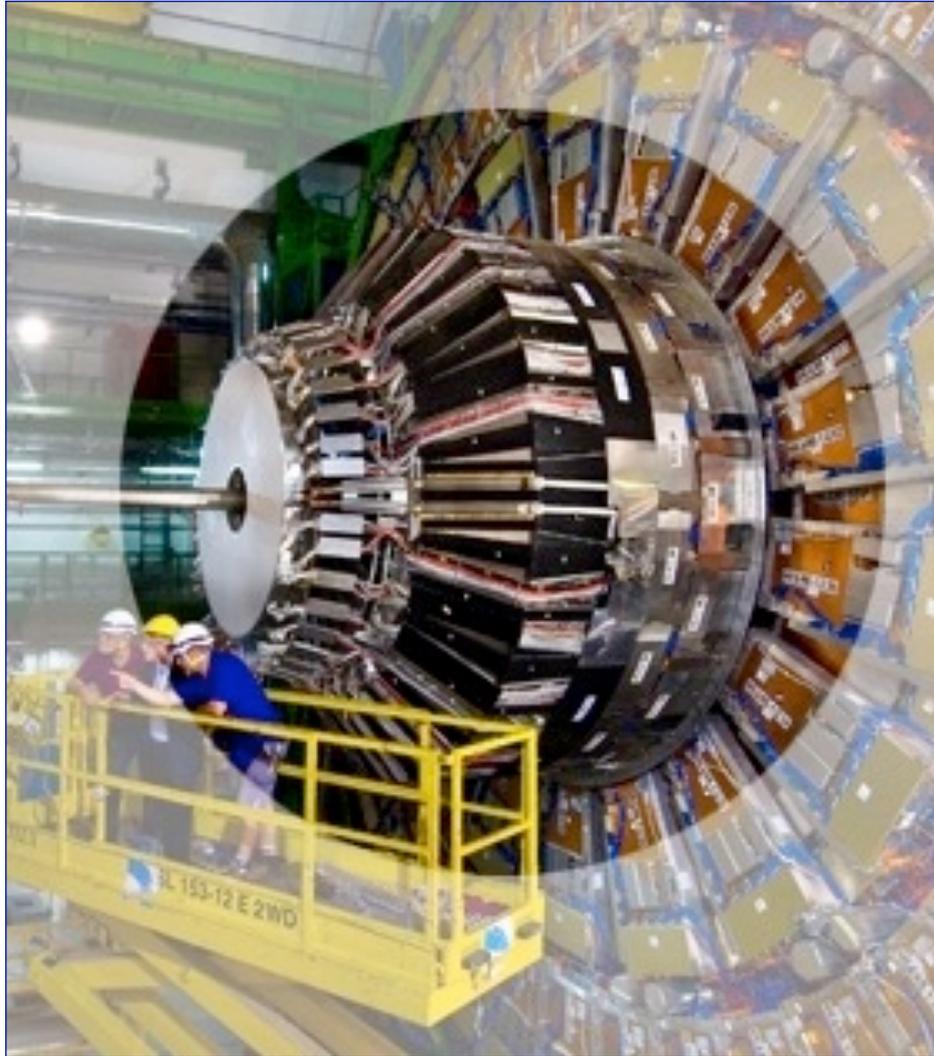
followed by **plastic scintillator tiles with direct SiPM readout**

for the lower radiation level region

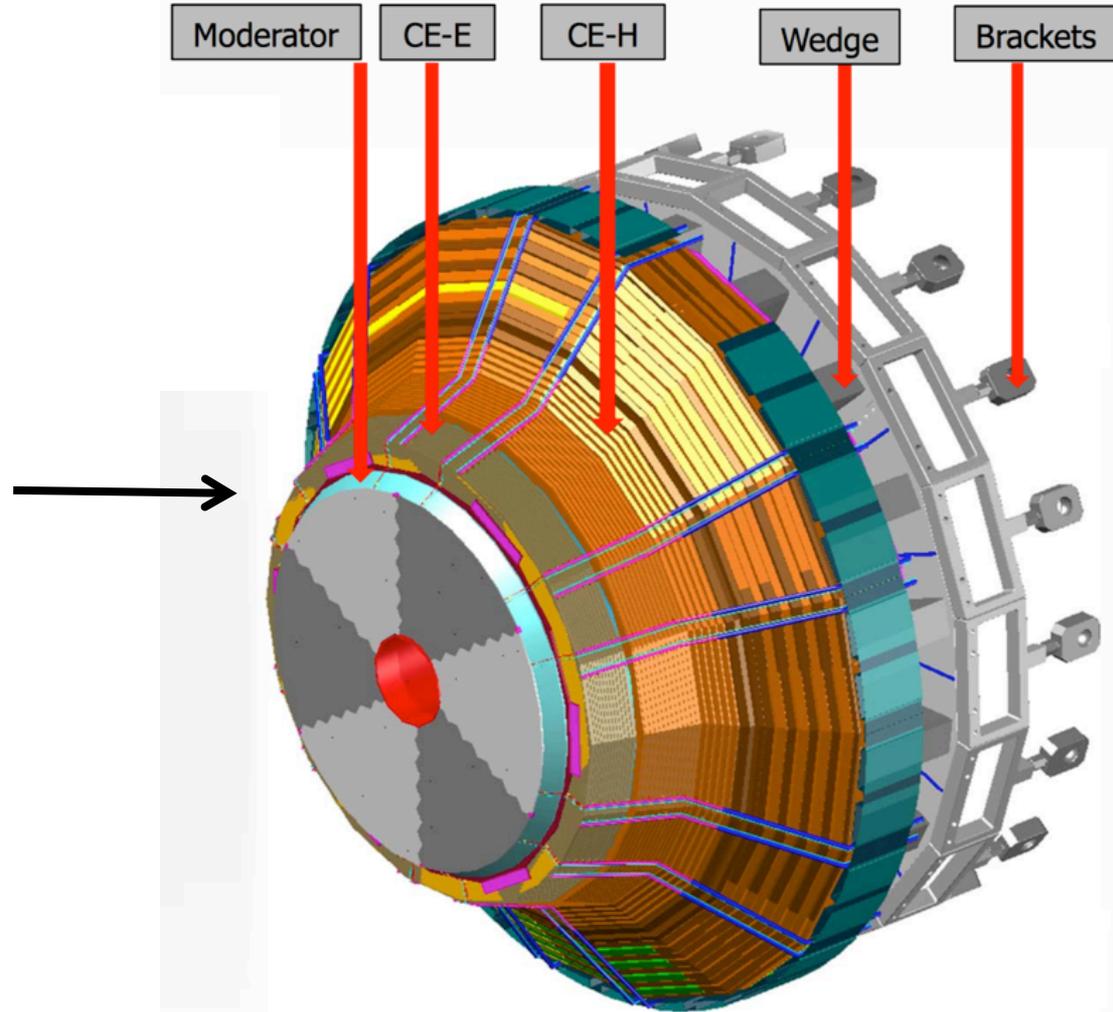
(absorber materials Cu & SS)

# HGCAL Mechanical Design

Present CMS endcap calorimeters



HGCAL design



**Remove** complete endcap calo. system and **replace** with HGCAL Calorimeter Endcap (CE), divided into CE-E and CE-H

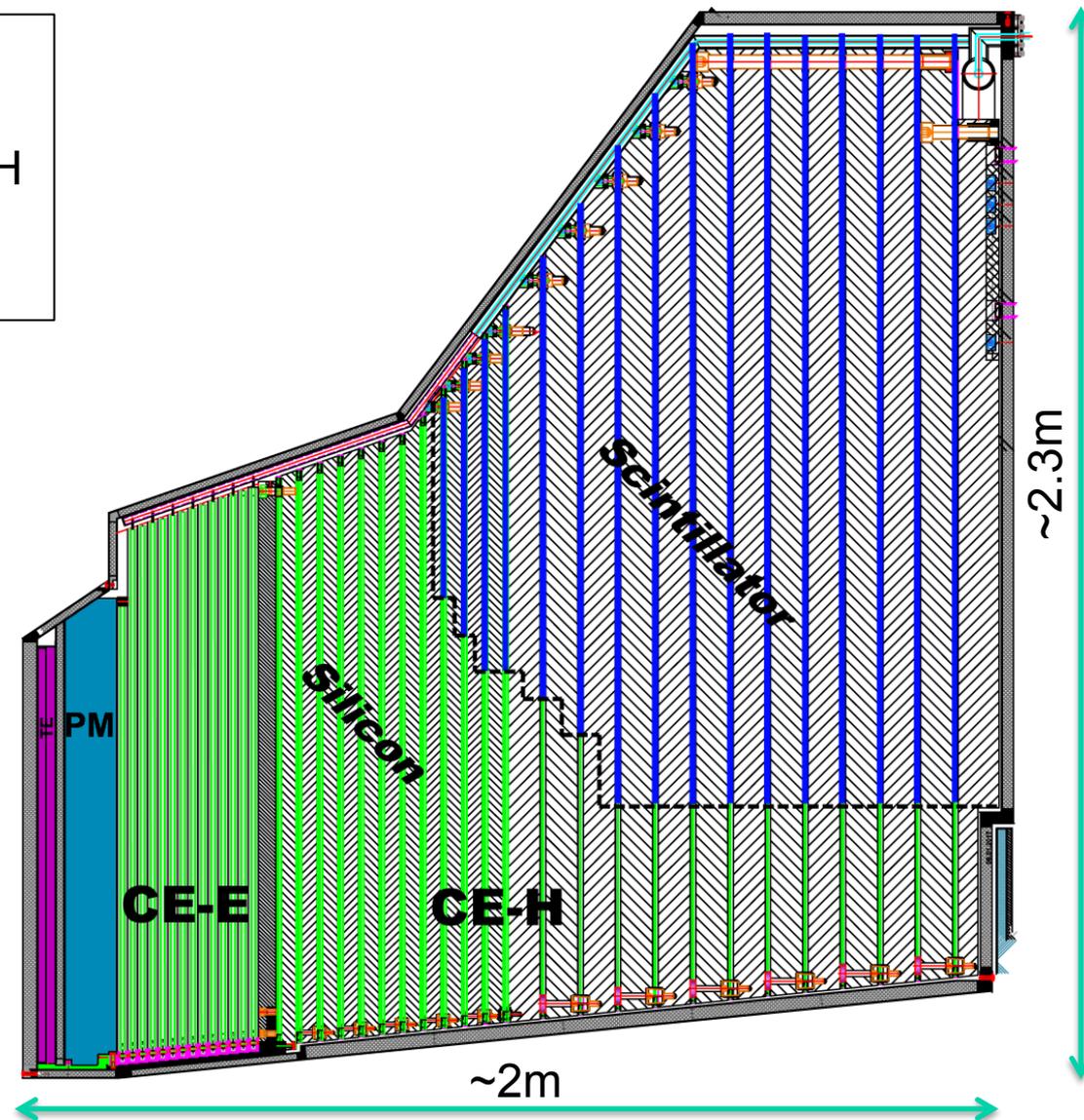
# CMS HGICAL: a 52-layer sampling calorimeter with unprecedented number of readout channels

## Active Elements:

- Hexagonal modules based on Si sensors in CE-E and high-radiation regions of CE-H
- Scintillating tiles with SiPM readout in low-radiation regions of CE-H

## Key Parameters:

- HGICAL covers  $1.5 < \eta < 3.0$
- Full system maintained at  $-30^{\circ}\text{C}$
- $\sim 600\text{m}^2$  of silicon sensors
- $\sim 500\text{m}^2$  of scintillators
- 6M Si channels,  $0.5$  or  $1.1\text{ cm}^2$  cell size
  - Data readout from all layers
  - Trigger readout from alternate layers in CE-E and all layers in CE-H
- $\sim 27000$  Si modules



EM calorimeter (**CE-E**): **Si**, Cu/CuW/Pb absorbers, 28 layers,  $26 X_0$  &  $\sim 1.7\lambda$   
Hadronic calo (**CE-H**): **Si** & **scintillator**, steel absorbers, 24 layers,  $\sim 9.0\lambda$

# ~600m<sup>2</sup> of silicon sensors (3x CMS tracker) in radiation field peaking at ~10<sup>16</sup>n/cm<sup>2</sup>

## Planar p-type DC-coupled sensor pads

- simplifies production technology; p-type more radiation tolerant than n-type
- ( consider n-type for 300 $\mu$ m sensors in lower radiation region of HGICAL )

## Hexagonal sensor geometry preferred to square

- makes most efficient use of circular sensor wafer
- reduces number of sensors produced & assembled into modules ( factor ~ 1.3 )

## 8" wafers preferable to 6"

- reduces number of sensors produced & assembled into modules ( factor ~ 1.8 )

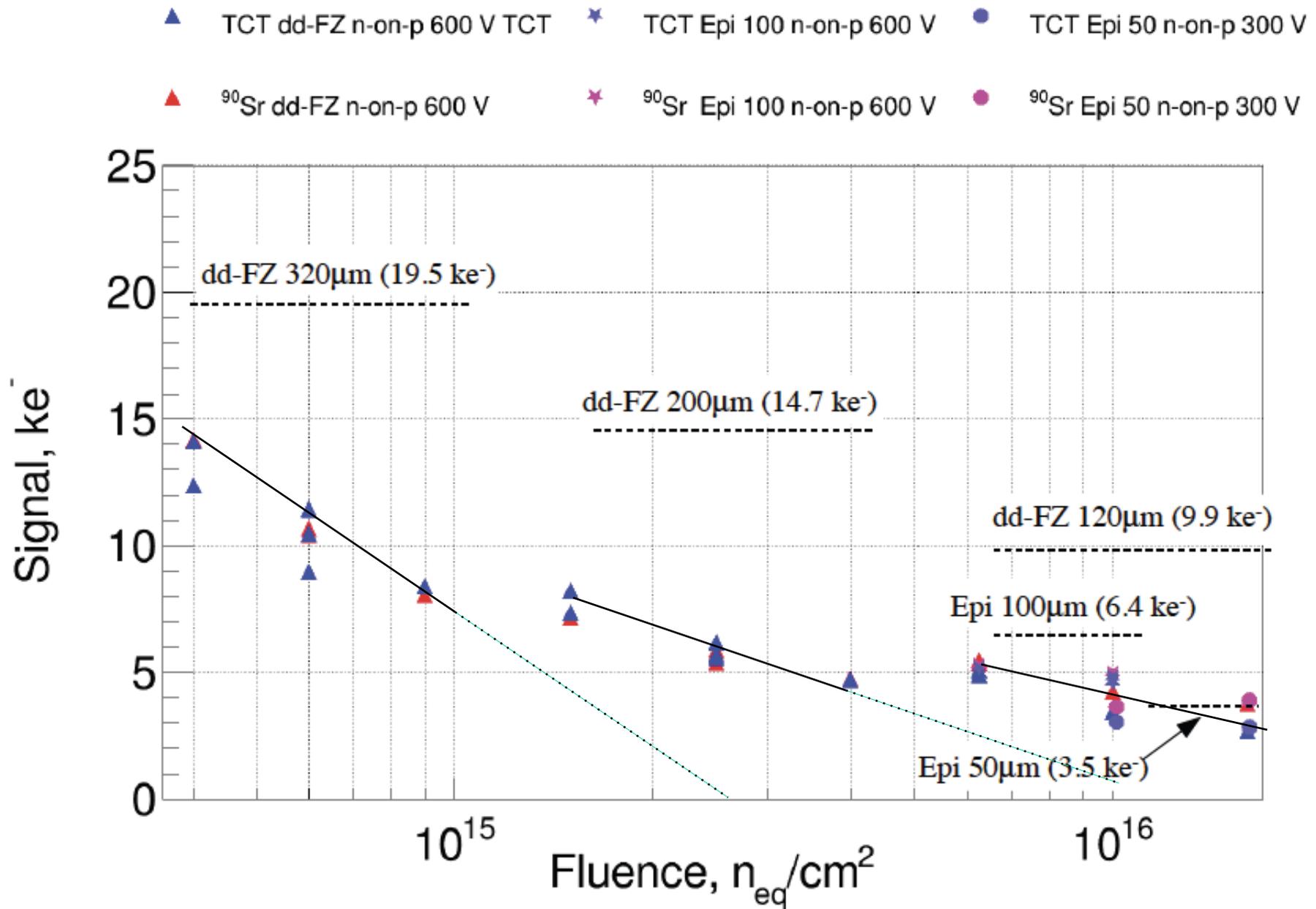
## 300 $\mu$ m, 200 $\mu$ m and 120 $\mu$ m active sensor thicknesses

- match sensor thickness (and granularity) to radiation field for optimal performance

## Simple, rugged module design & automated module assembly

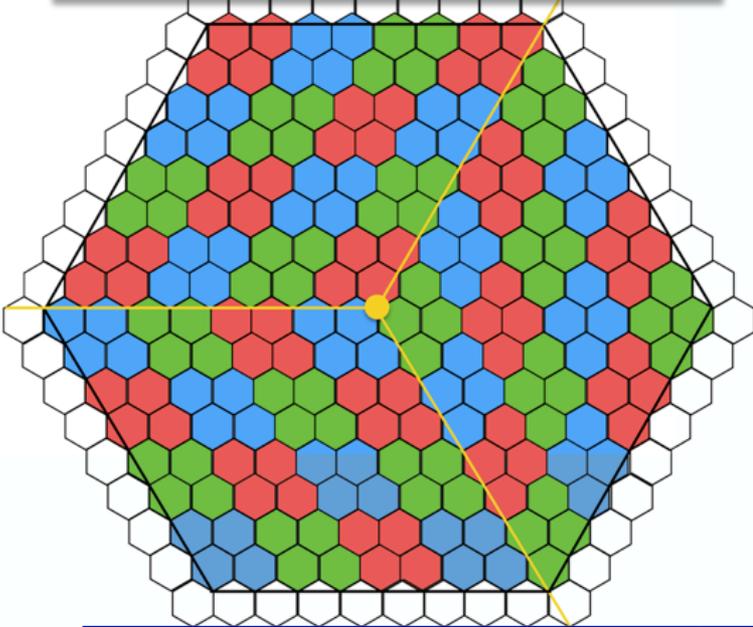
- provide high volume, high rate, reproducible module production & handling

# Thinner sensors: less decrease in charge collection efficiency

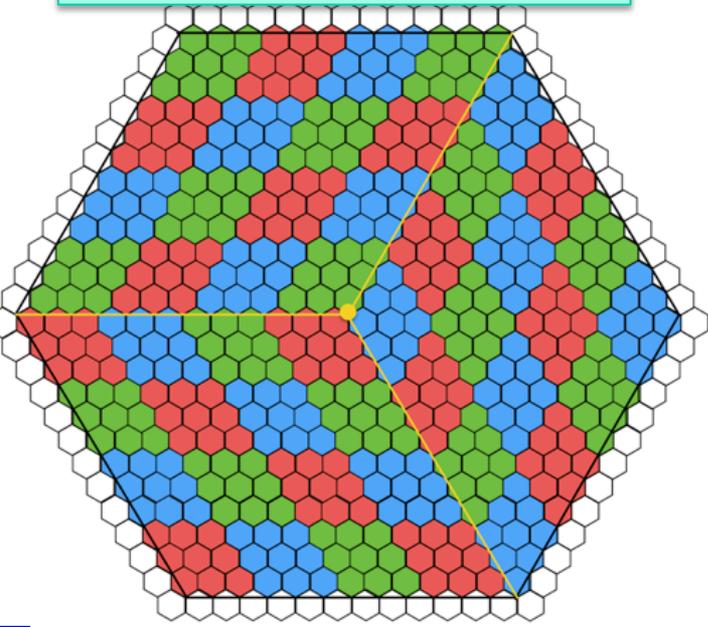


# 8" silicon sensors will be hexagonal, divided with 3-fold symmetry into hexagonal cells

300/200 $\mu\text{m}$ : 192 cells/sensor



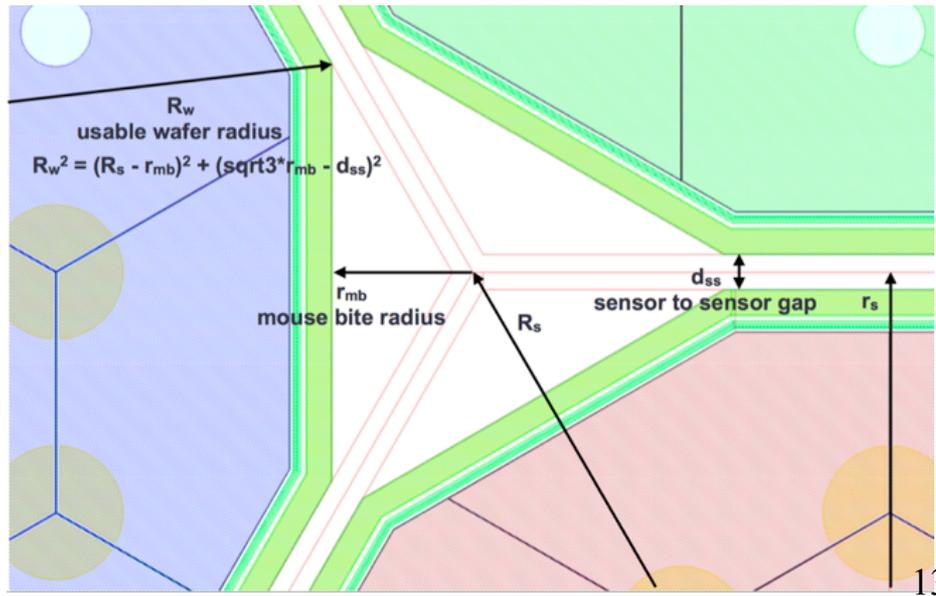
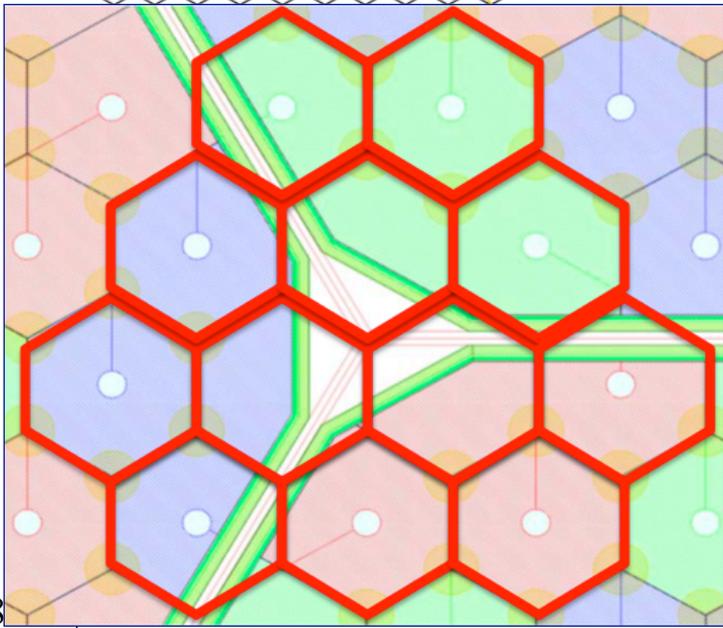
120 $\mu\text{m}$ : 432 cells/sensor



$\varnothing \sim 190\text{mm}$

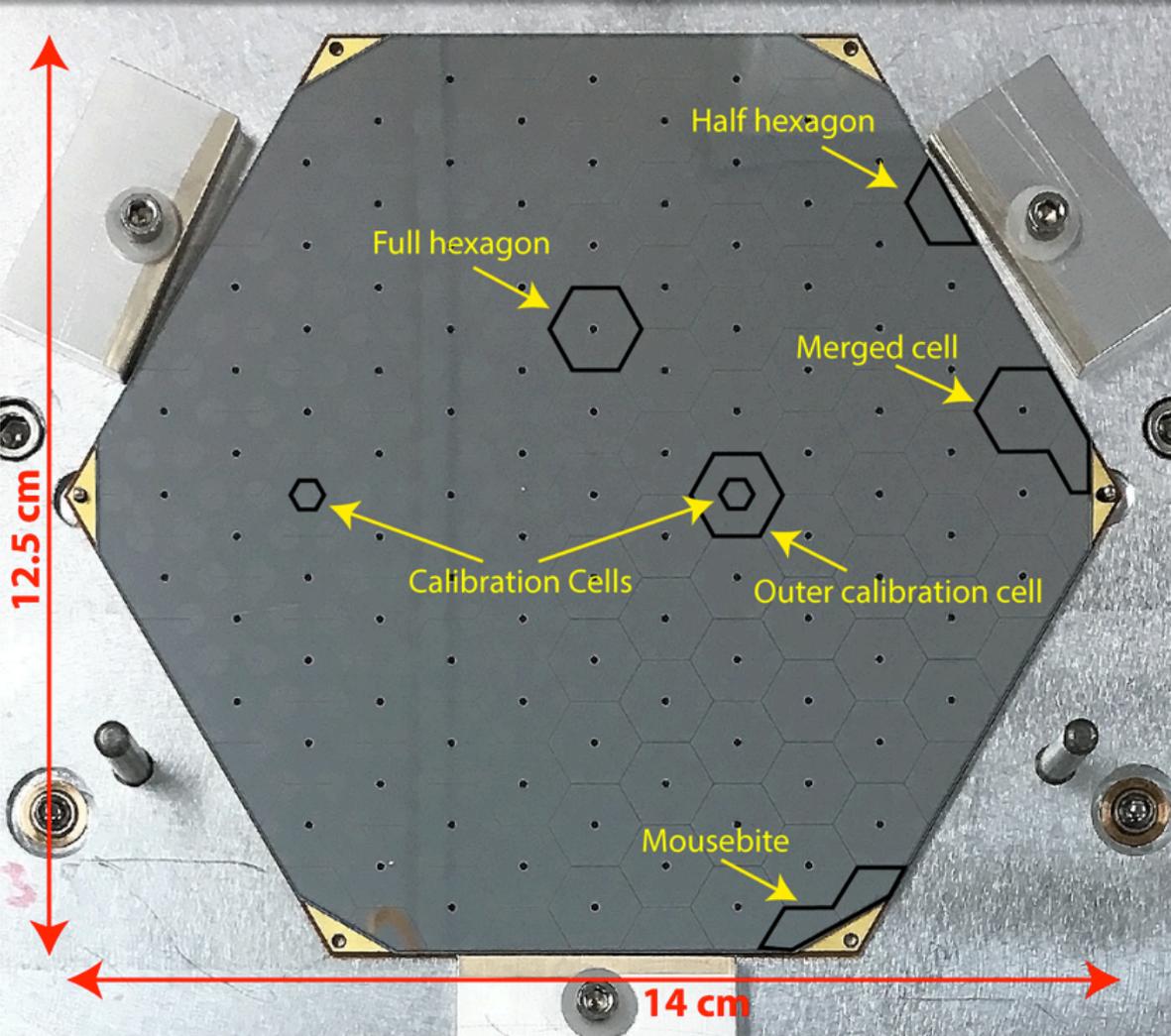
All cells have  $C \leq 65\text{pF}$

Coloured groupings of cells represent "trigger cells"



# Sensors divided in hexagonal cells + some special cells

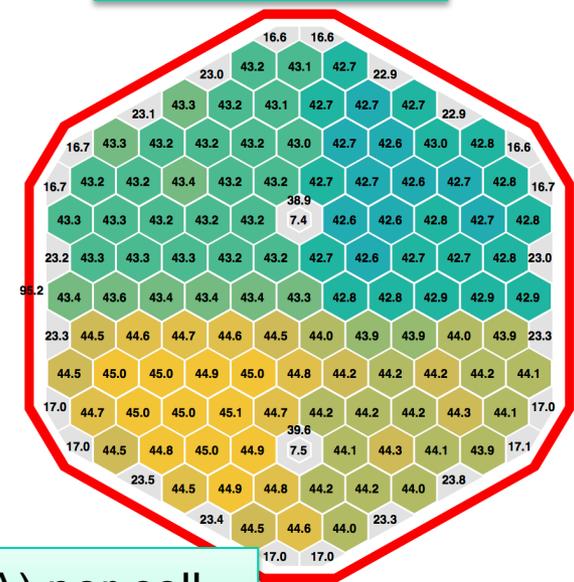
6" prototype sensor, with 4 quadrants of inter-cell spacing



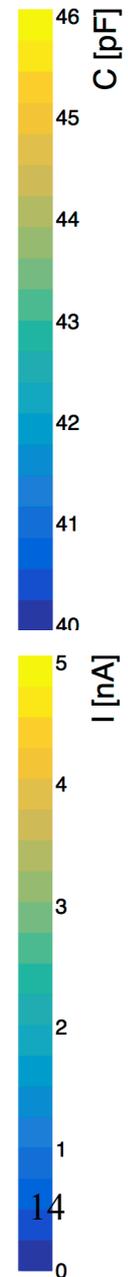
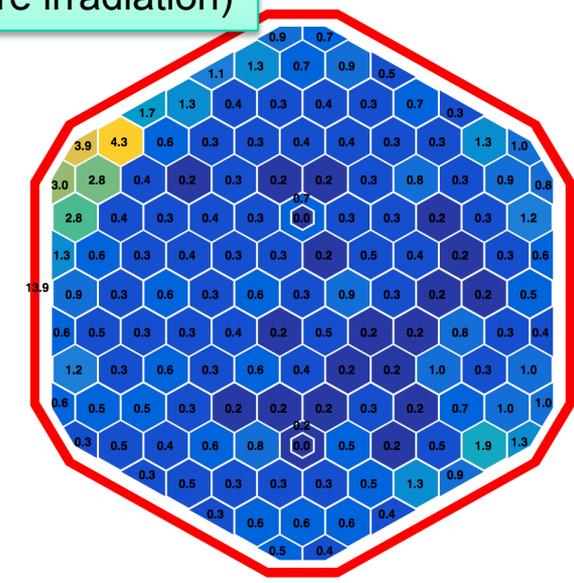
Prototype 6" and 8" sensors made by three producers

28-May-2018

~55pF per cell



O(nA) per cell (before irradiation)

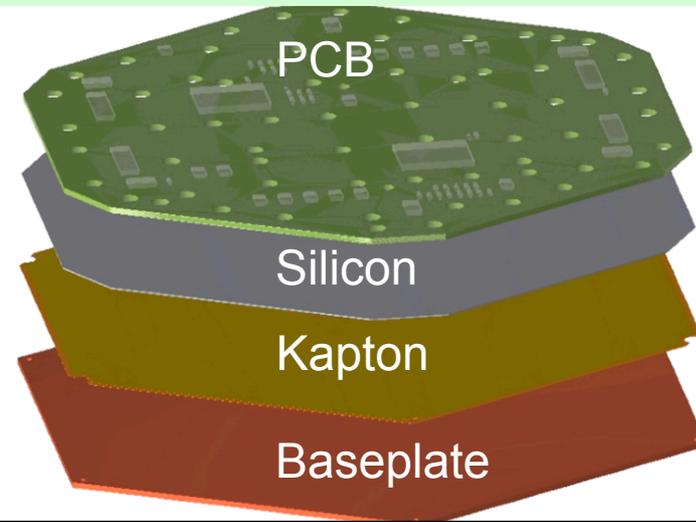
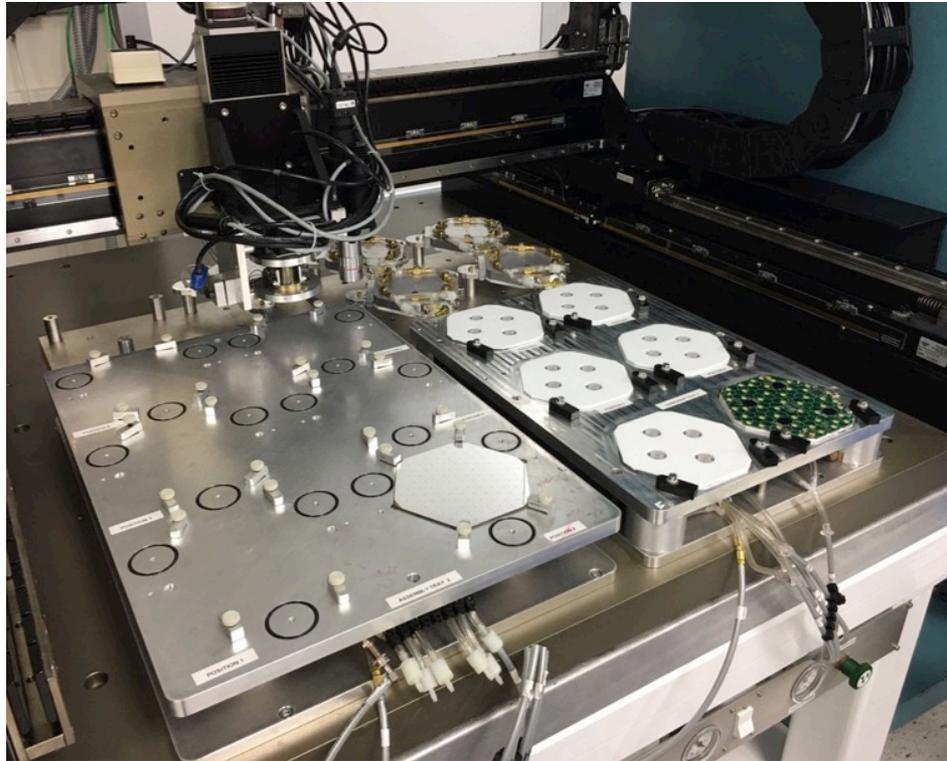


Values for U = 300.0 V

Values for U = 1000.0 V

# Si modules are glued assemblies

Automated gantry @ UCSB  
used previously for CMS tracker assembly



In CE-E, baseplate = 1.2mm CuW, to  
keep overall density high

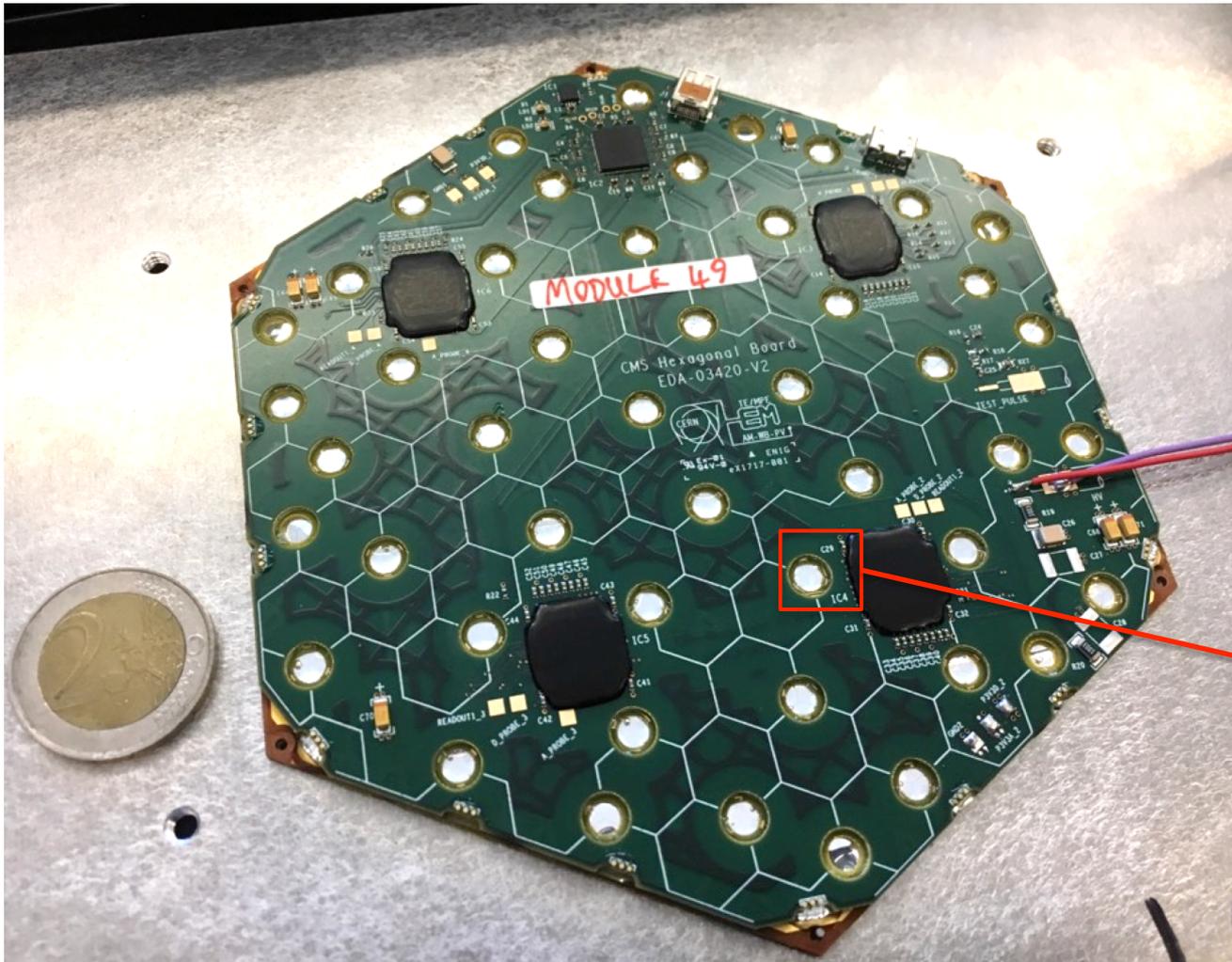


Three centers are being setup in Asia:  
India, China (IHEP), **Taiwan (NCU/NTU)**

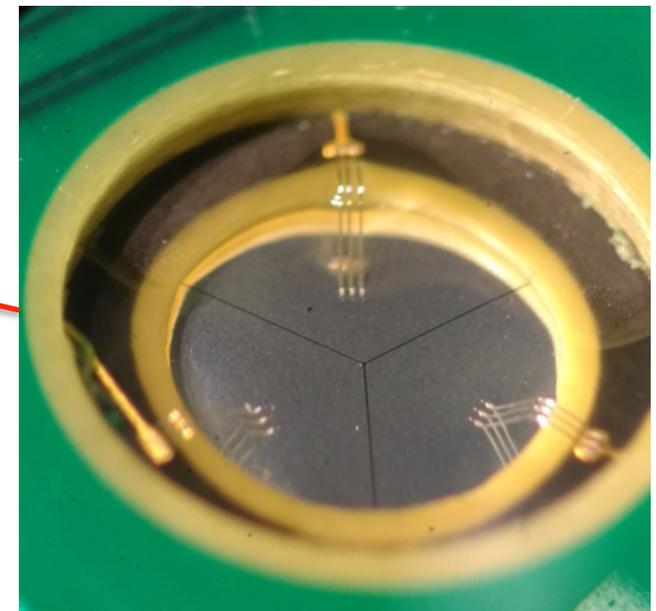
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# 27000 modules with 0.5-1cm<sup>2</sup> pads

Silicon sensor glued to baseplate and PCB containing FEE

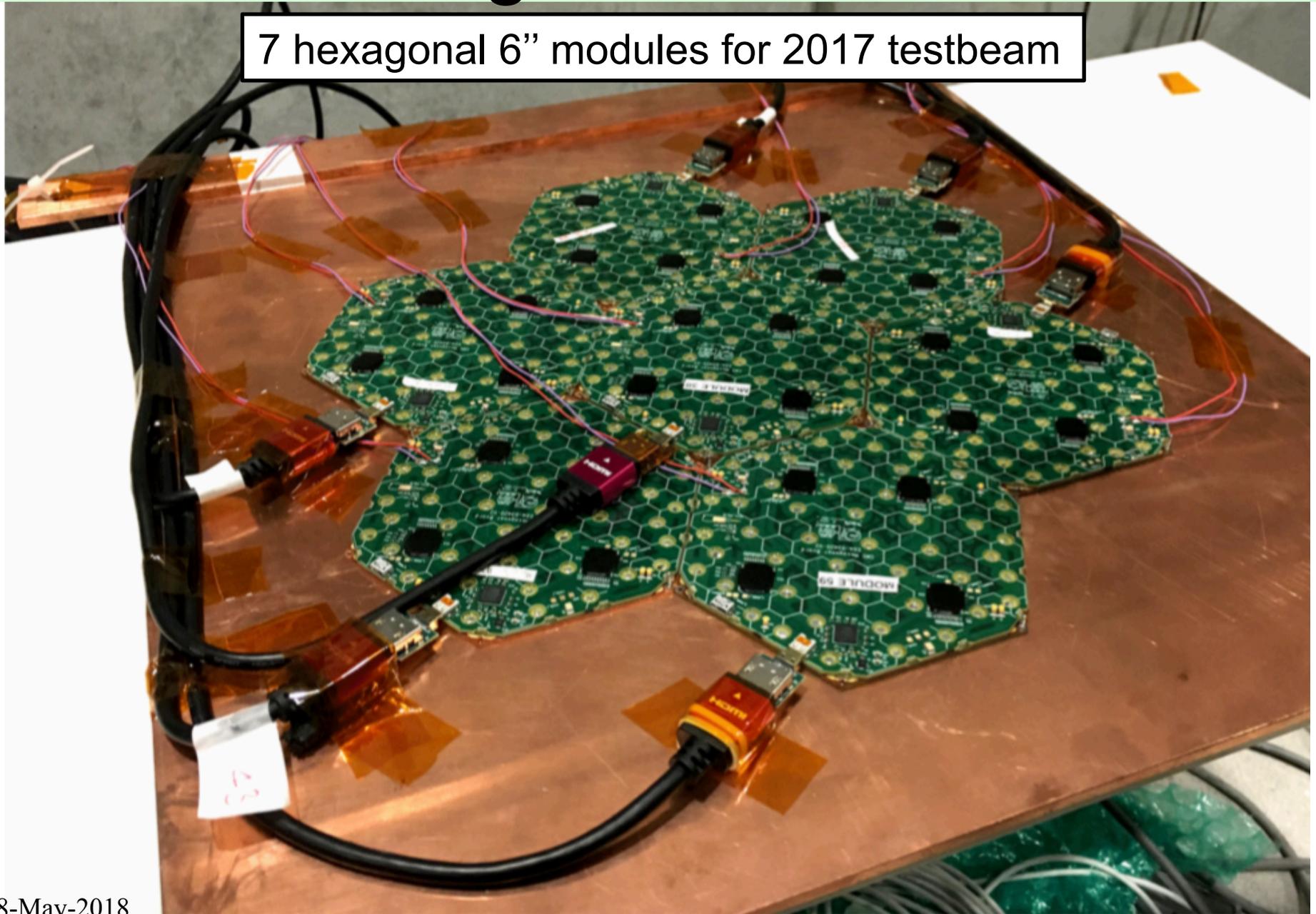


Wire bonding from PCB to silicon through holes

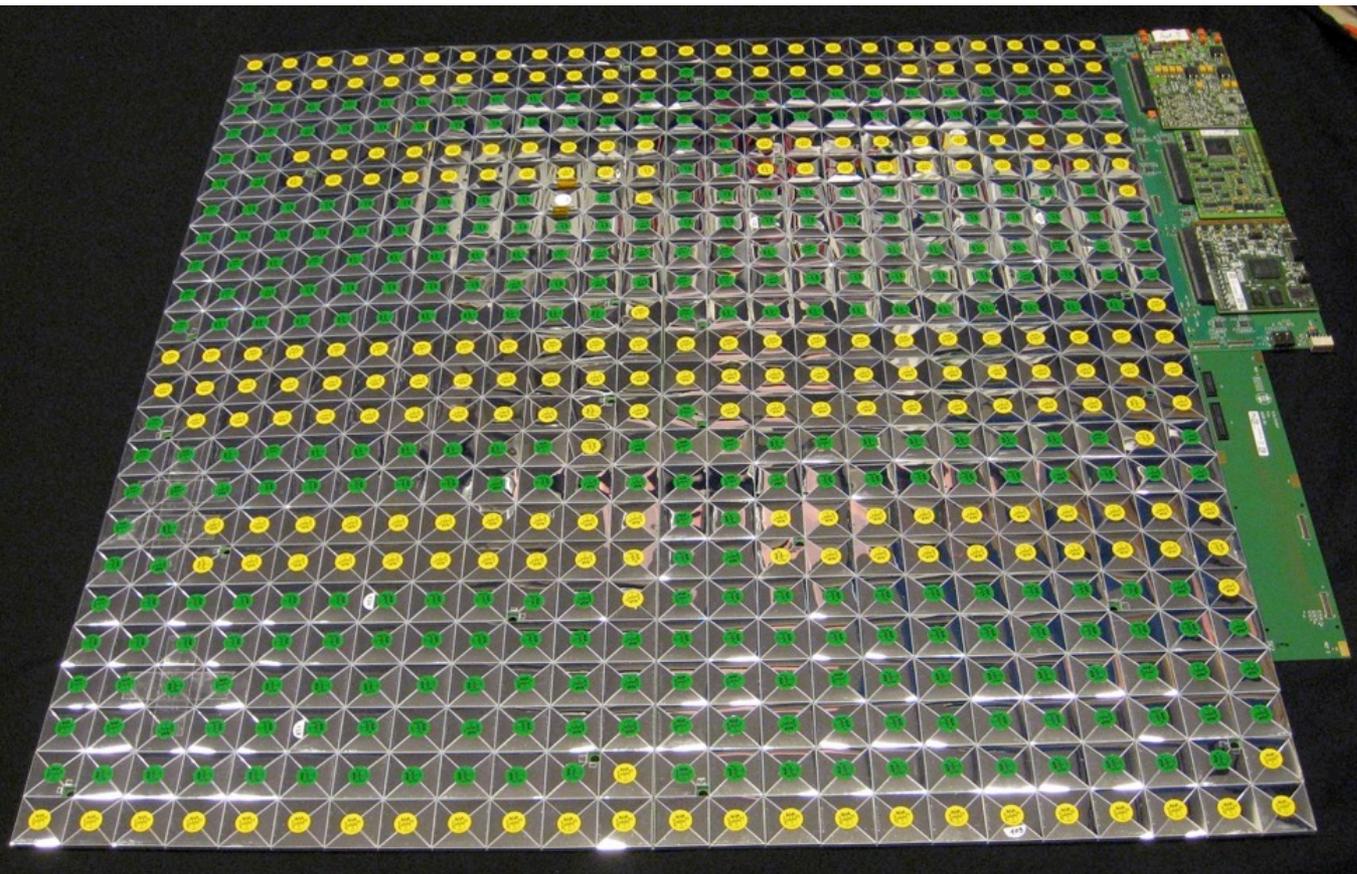


# Si Modules arranged in hexagonal matrices

7 hexagonal 6" modules for 2017 testbeam



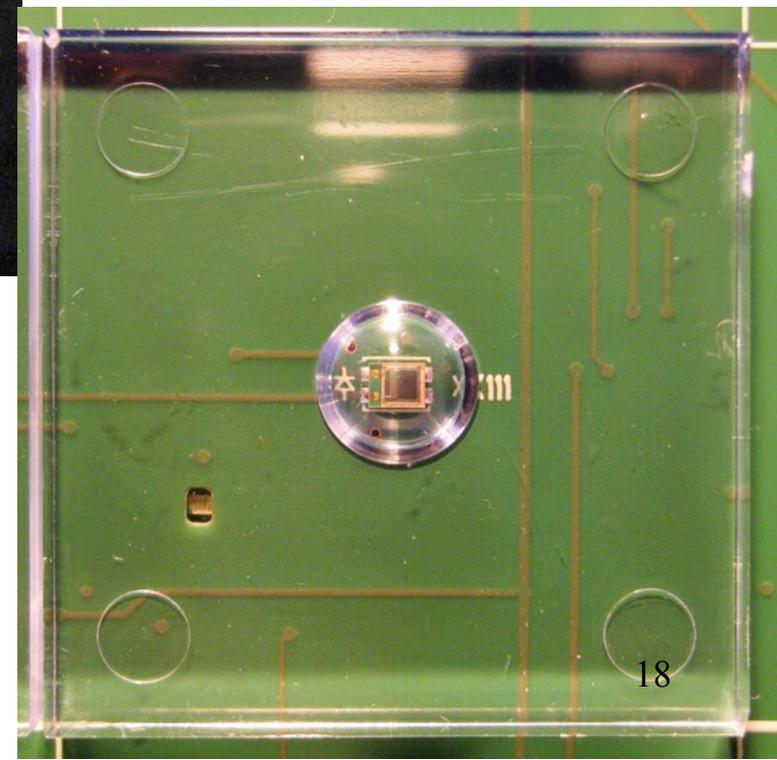
# HGCAL will also include 500m<sup>2</sup> of scintillator tiles with on-tile SiPM readout



SiPMs already used successfully in e.g. CMS HCAL Phase 1 upgrade

Tile boards or “megatiles” limited in size by CTE of different components

For first beam tests, modified CALICE AHCAL used for rear hadron calorimeter:  
3x3cm<sup>2</sup> scintillator tiles + direct SiPM readout

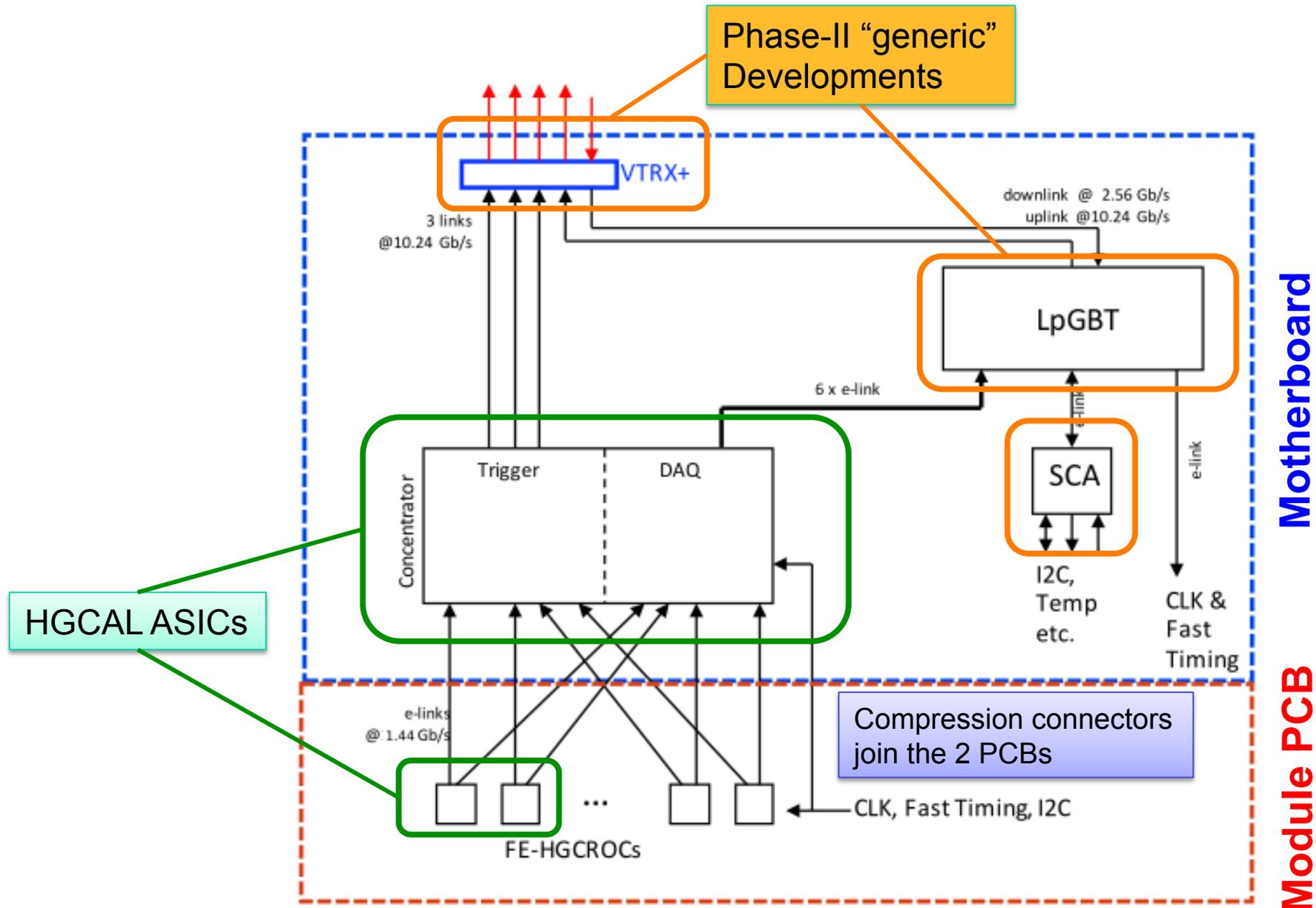


# The FE electronics are particularly challenging in the compact HGCAL

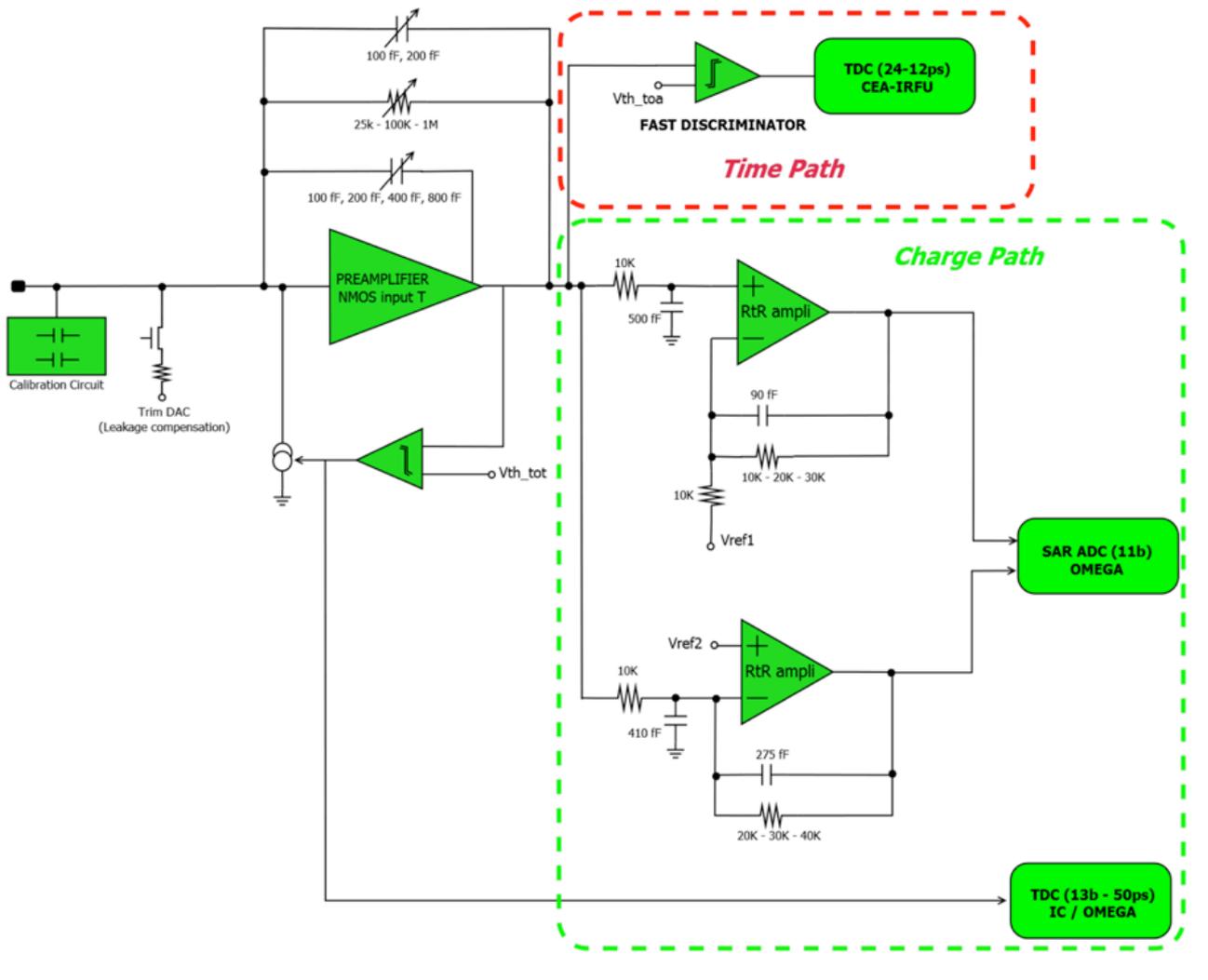
- Low noise ( $<2500e^-$ ) and high dynamic range ( $\sim 0.2\text{fC} \rightarrow 10\text{pC}$ )\*
  - See **MIPs** ( $\sim 3.5\text{fC}$  in  $300\mu\text{m}$  silicon) **with S/N > 2** for whole lifetime of HL-LHC
  - Use 130nm CMOS with 1.5V supply
- Provide timing information to tens of picoseconds
  - Need clock distribution jitter 10-15ps (same specs as for other CMS detector upgrades)
- Have fast shaping time ( $<20\text{ns}$ ) to minimize out-of-time pileup
- On-detector digitization, data concentration and zero suppression
- On-detector creation of trigger sums
- Buffering of data to accommodate  $12.5\mu\text{s}$  L1 latency
- High-speed readout links to interface with 10 Gb/sec IpGBT chipset
- $<20\text{mW}$  per channel (roughly limited by cooling power)
- High radiation resistance ( $\sim 2\text{MGy}$  and  $10^{16} n_{\text{eq}}/\text{cm}^2$ )
- And be in production  $\sim 2021$

28-May-2018 \*want S/N >4 at beginning of HL-LHC for 1 MIP in  $120\mu\text{m}$  silicon  $\sim 1.5\text{fC}$ ;  
upper limit from 1.5 TeV photon shower producing  $\sim 6000$  MIPs in a single cell<sup>19</sup>

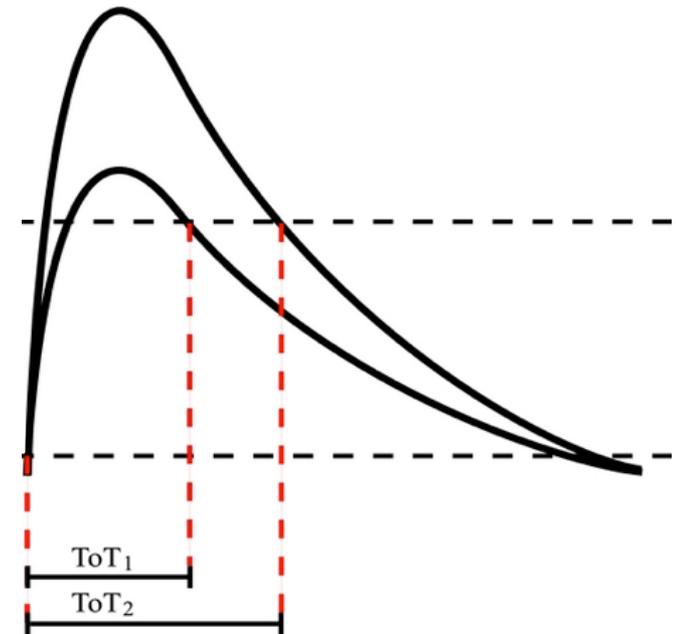
# On-detector electronics are a mixture of HGCal-specific ASICs and “generic” developments



# HGCROC: includes ToT (low power high dynamic range), ToA (timing) and on-chip ADC/TDC

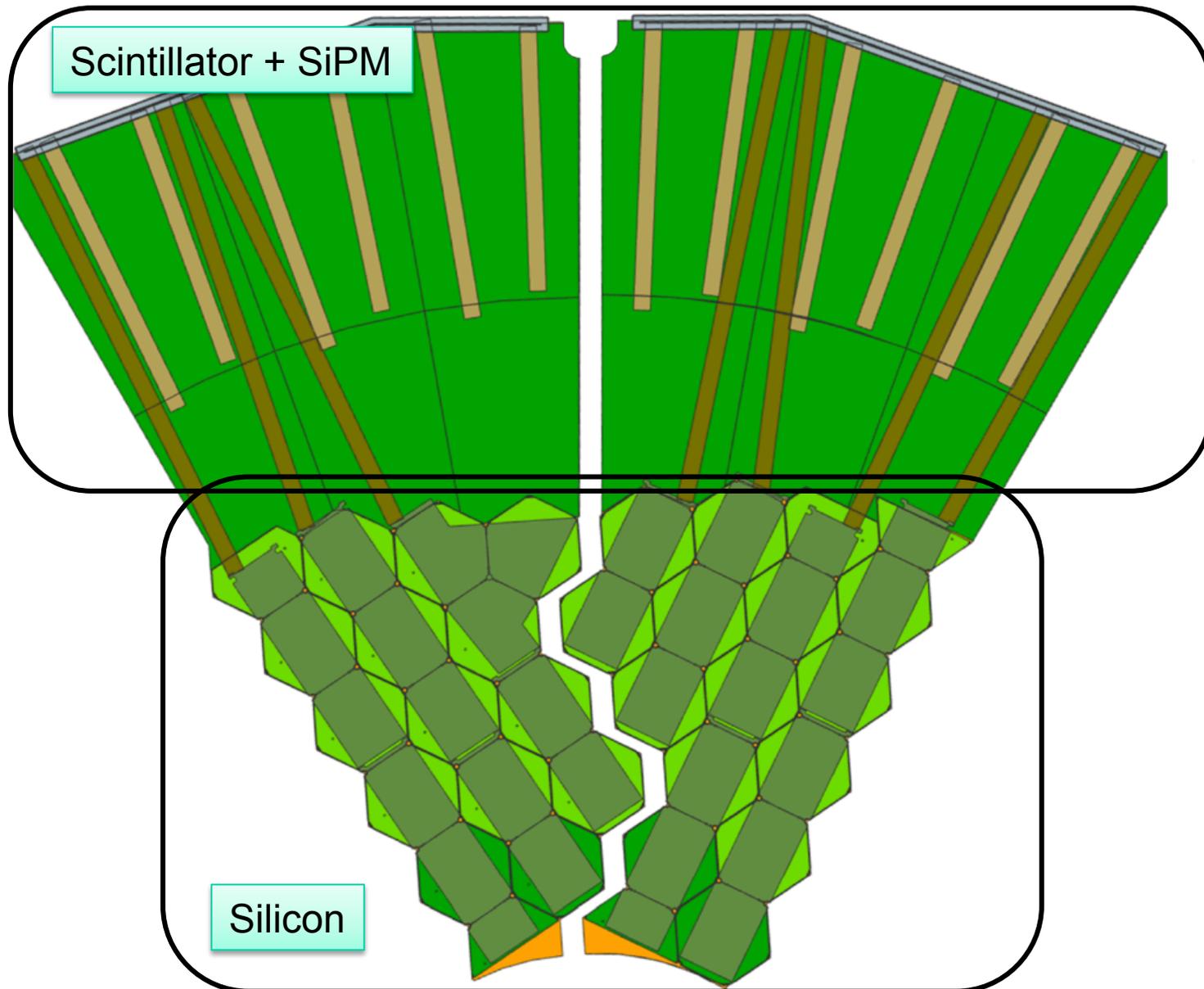


Time over threshold:  
Proportional to pulse height

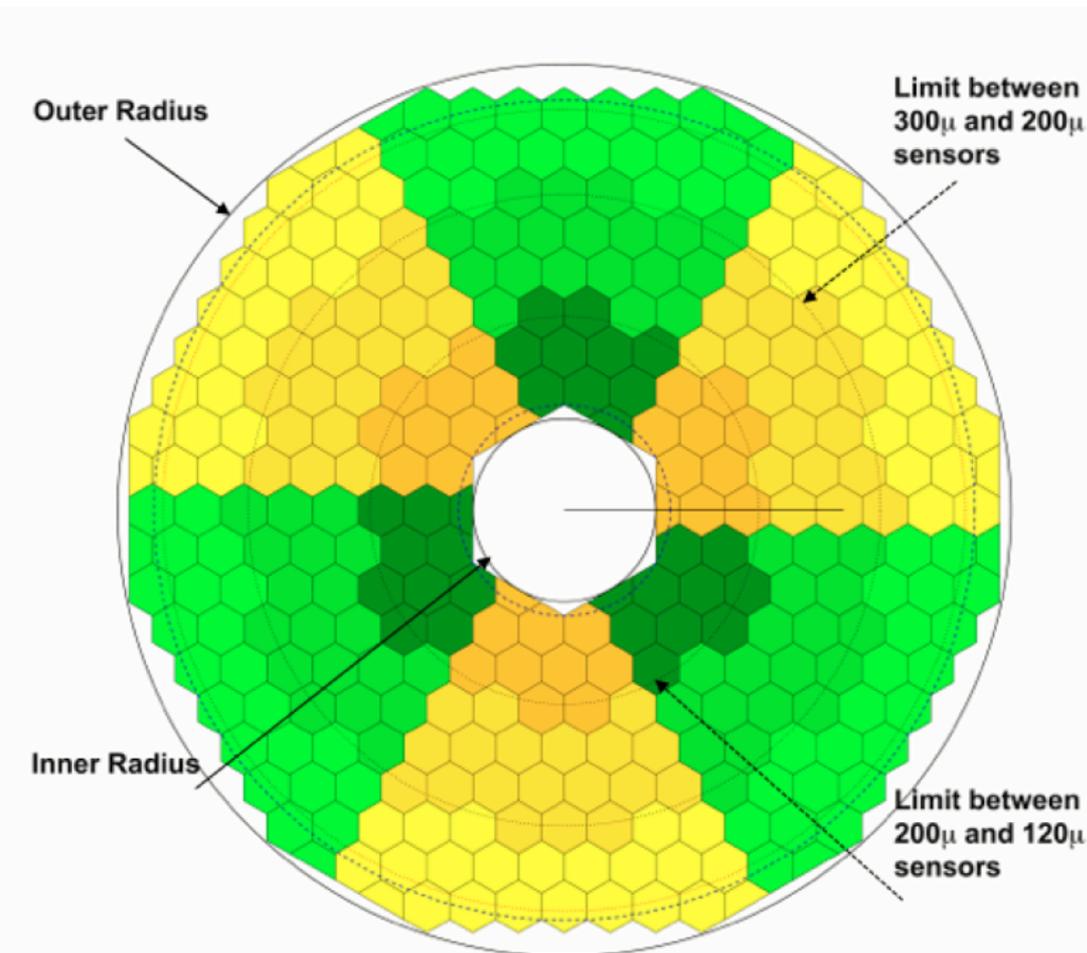


Skiroc2-CMS ASIC (2017) already had some of these features, inc. ToT  
First simplified HGCAL ASIC (HGCROCV1) in 130nm CMOS being tested now

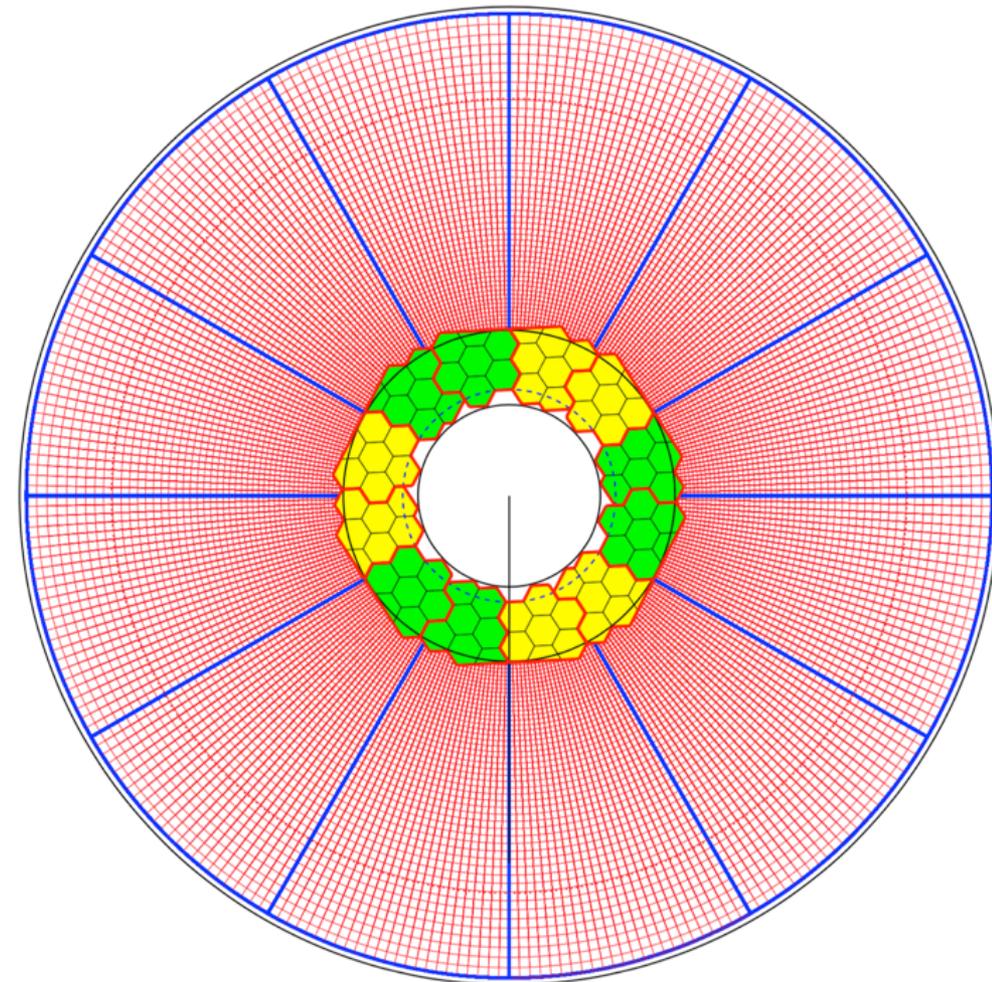
# CE-H cassettes: some have all silicon (*a la* CE-E); some have mixture of Si and scint/SiPM



# Wedge-shaped “Cassettes” containing arrays of silicon modules or silicon+scintillator/SiPM

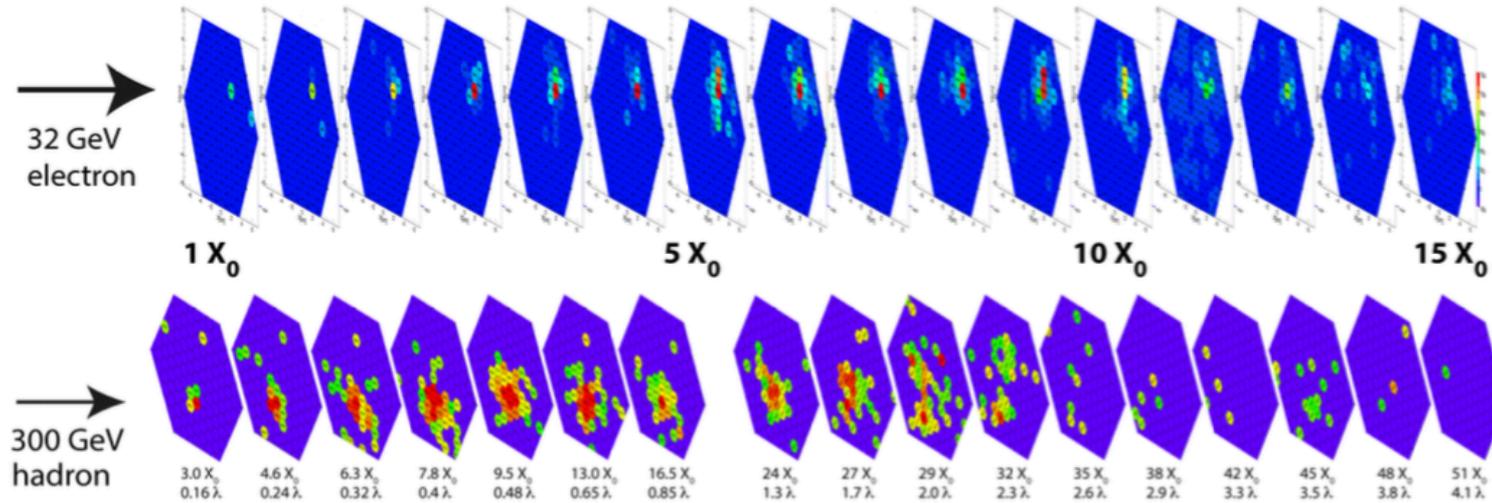


Silicon-only layer (in CE-E) showing “cassettes” and different sensor thicknesses

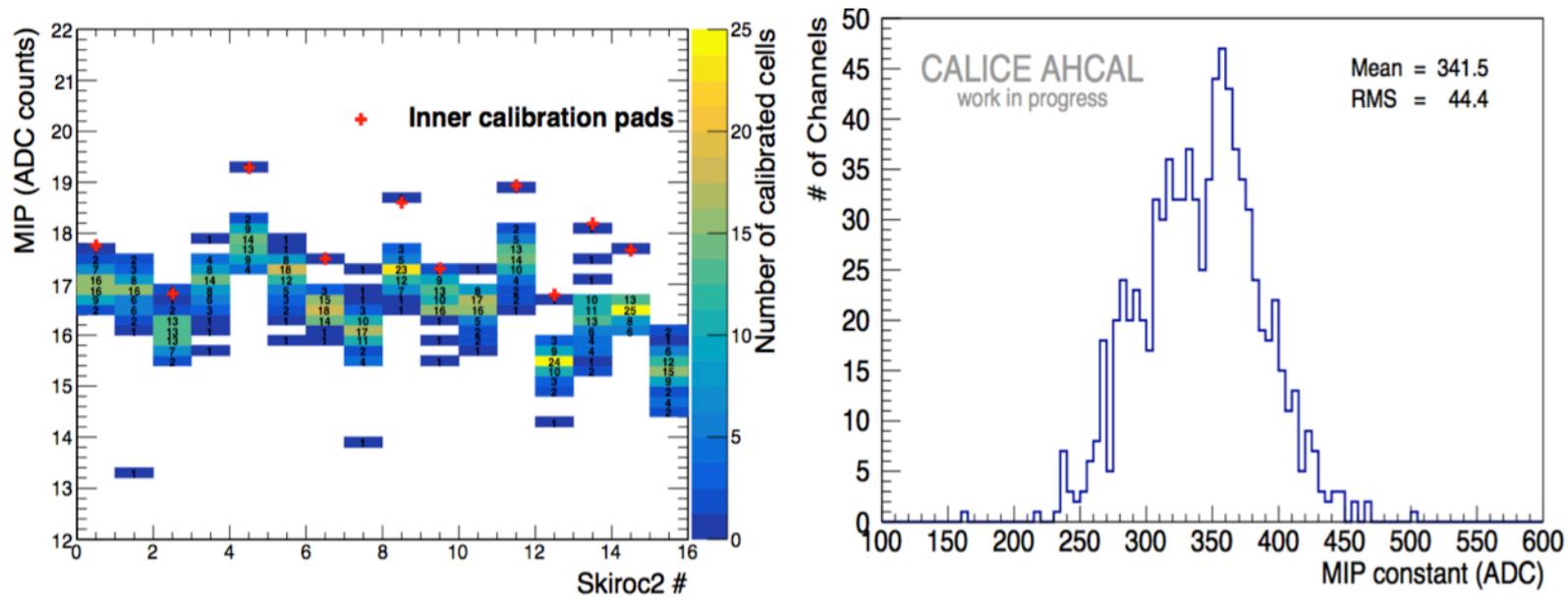


Mixed layer (in CE-H) with silicon at high  $\eta$  and scintillator+SiPM at low  $\eta$

# Prototypes tested in 2016-17 beam tests: validated basic design, good stability



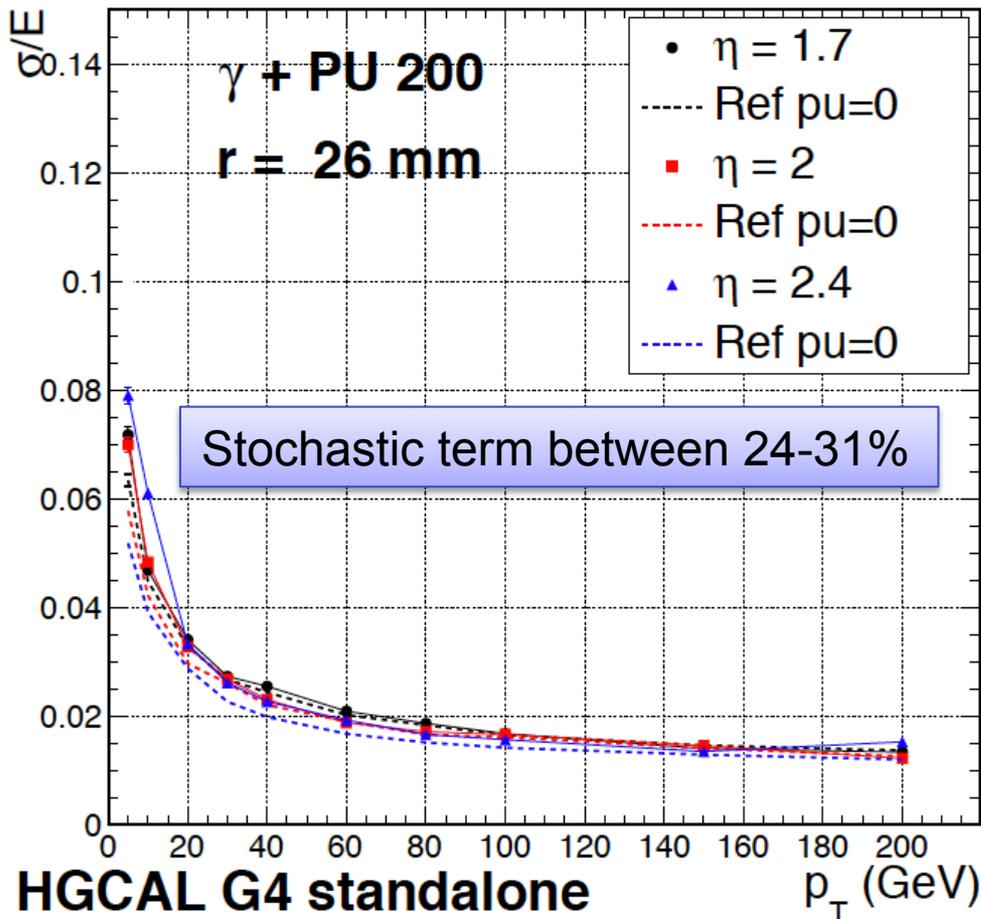
Feng Wang's presentation



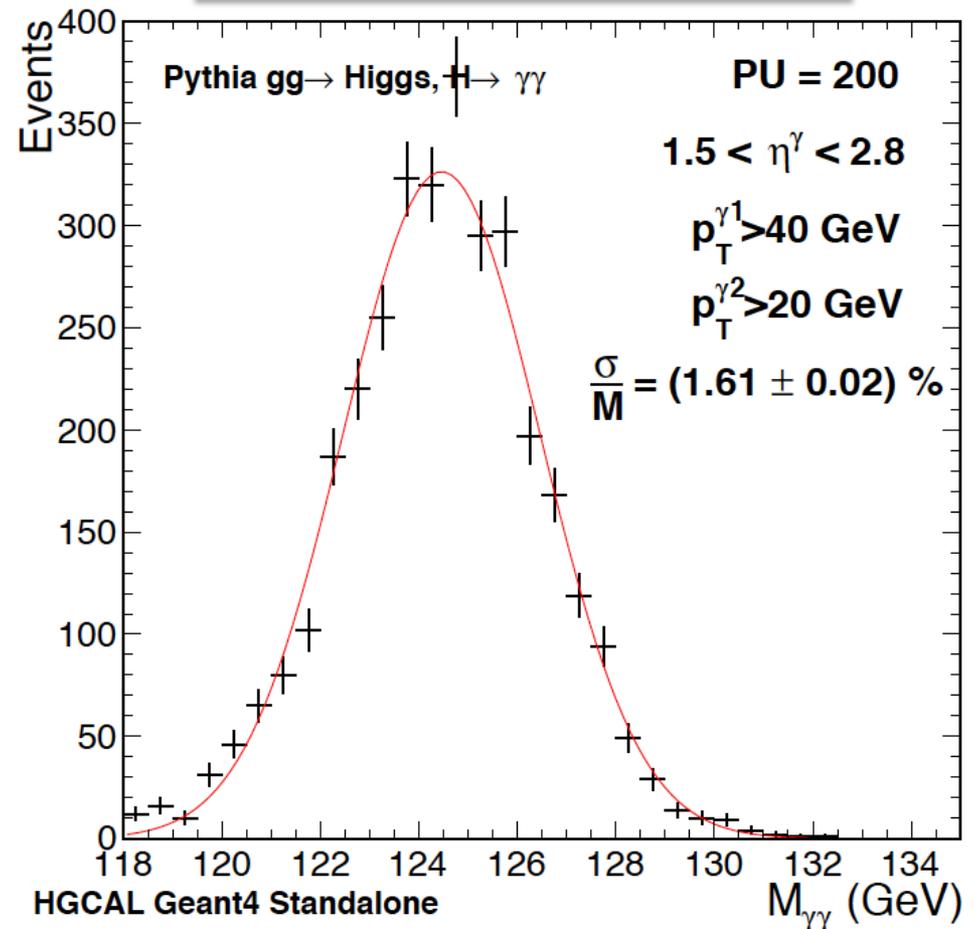
MIPs from muons seen in all parts, single particles seen within showers.

# G4 simulation used to predict performance of HGCAL in presence of pileup: $e/\gamma$ resolution

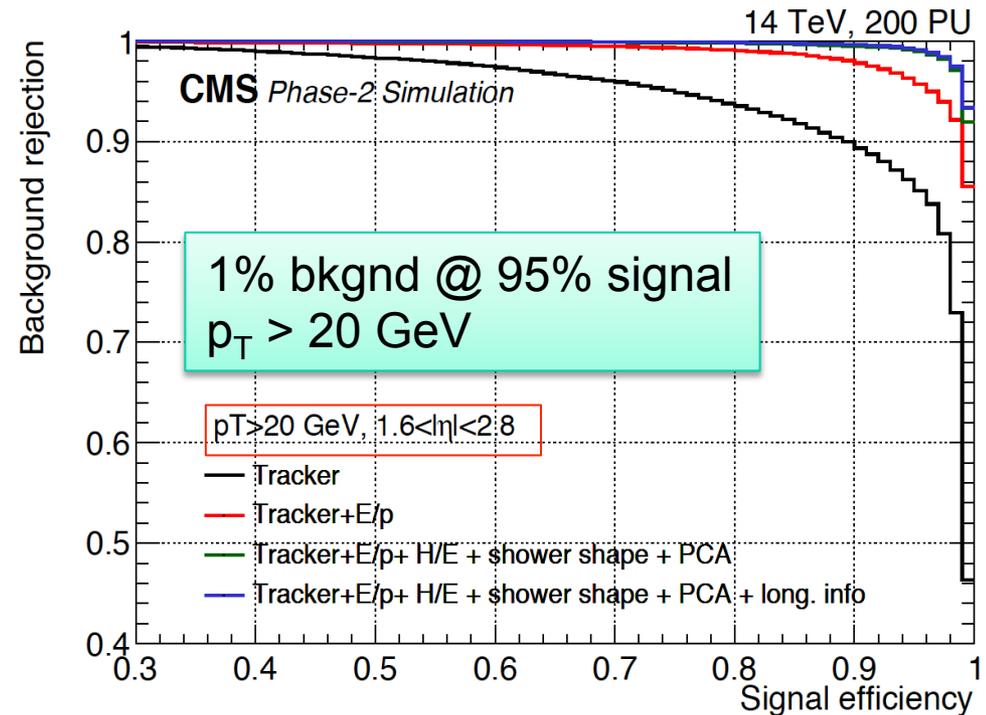
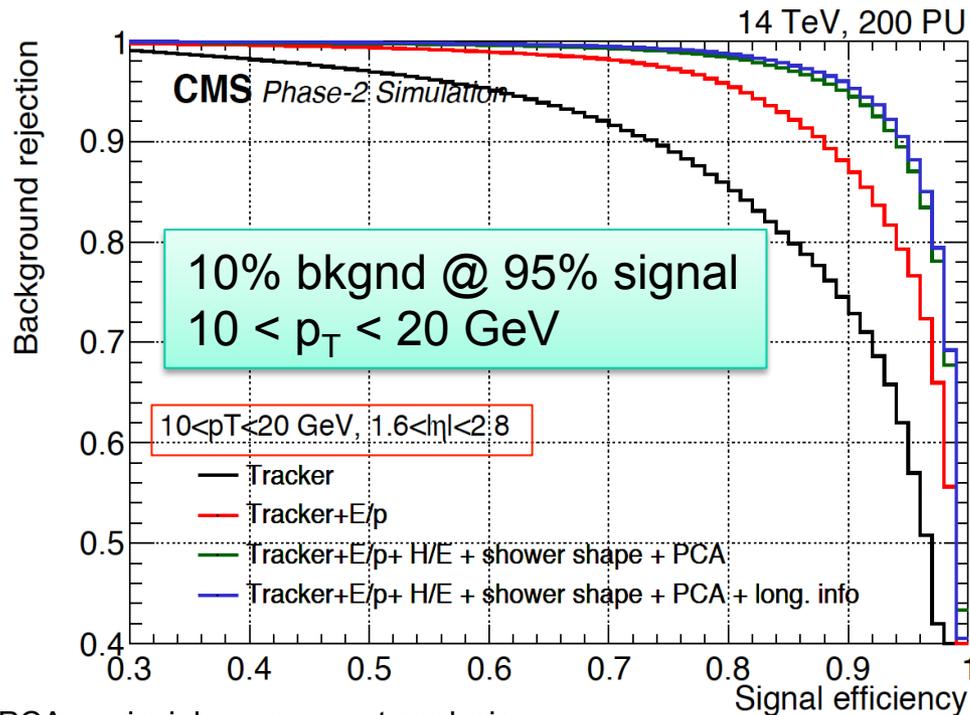
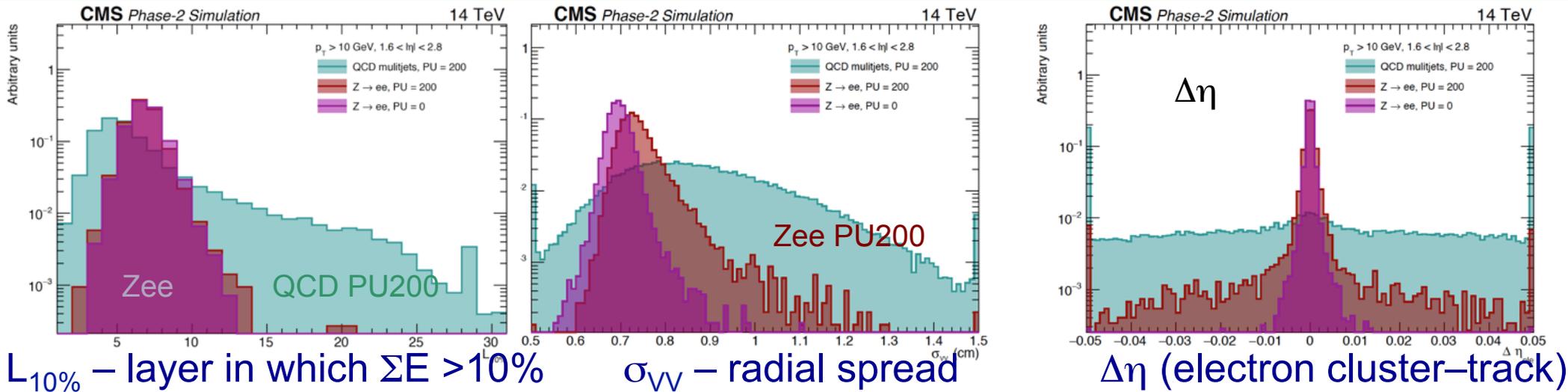
Single unconverted  $\gamma$  in CE-E reconstructed in  $r < 2.6\text{cm}$   
 → **insensitive to pileup**



H- $\gamma\gamma$ , both  $\gamma$  in HGCAL  
 ( $\gamma$  do not convert in TK)  
 Pileup 200



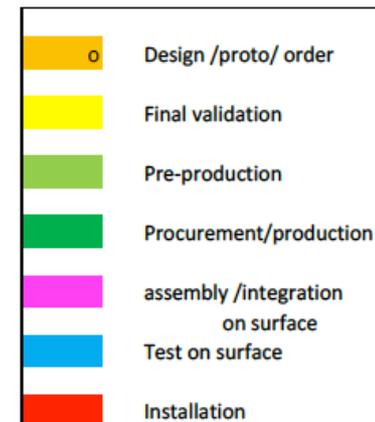
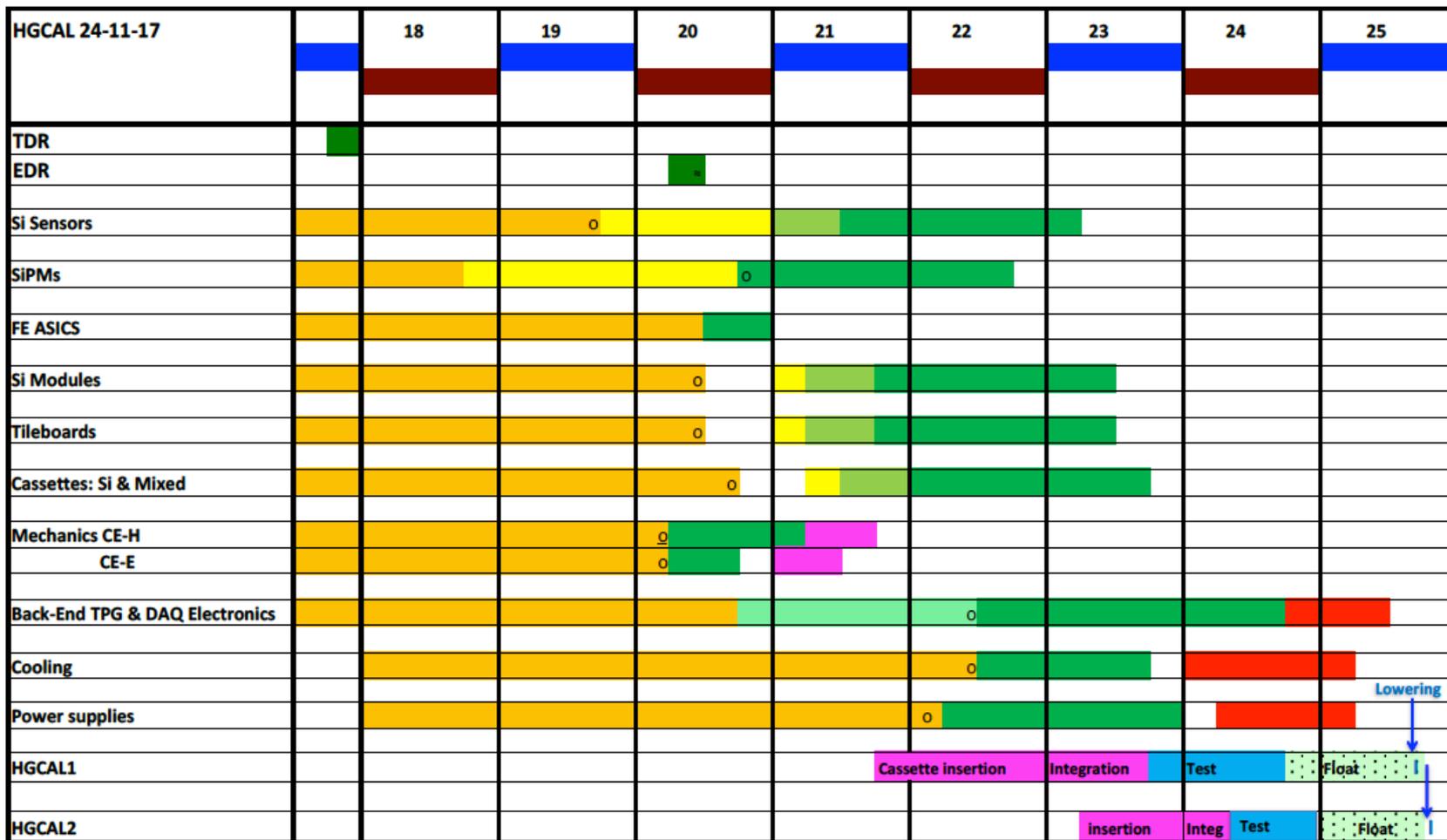
# e-id greatly improved using shower-shape information from HGCAL



\*PCA = principle component analysis

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# HGCAL schedule: 5 years to complete



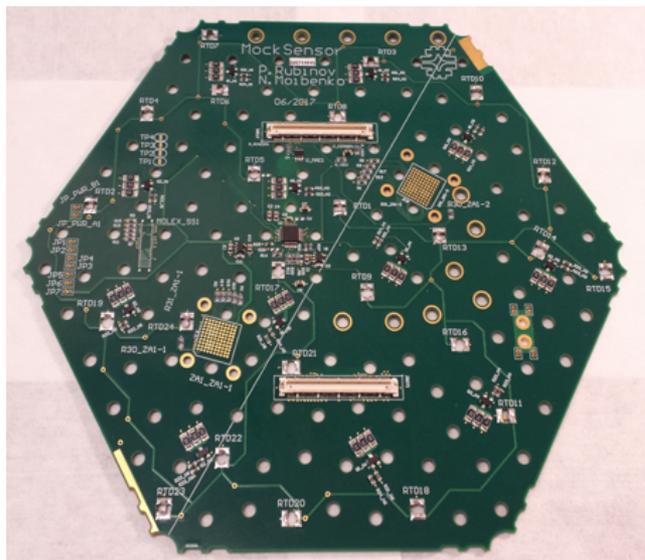
Challenging times ahead.

# Summary

- The High Granularity CALorimeter is the CMS choice for the forward end-cap region.
- HGCAL will provide unprecedented number of readout/trigger channels/layers, including timing, while capable of dealing with pileup and high radiation levels.
- The project comes with technological and engineering challenges: an experimentalist paradise.

# Extra Slides

# “dummy” cassette being assembled with PCBs containing only connectors and heat loads



8” hexagonal PCBs glued to silicon and baseplates → **modules**

3 modules connected to a single “**motherboard**” providing power, data concentrator and optical links

